



New 8FX 8-bit Microcontrollers

The MB95630H Series is a series of general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers of this series contain a variety of peripheral functions.

Features

- F2MC-8FX CPU core
 - □ Instruction set optimized for controllers
 - · Multiplication and division instructions
 - · 16-bit arithmetic operations
 - · Bit test branch instructions
 - · Bit manipulation instructions, etc.

■ Clock

- □ Selectable main clock source
 - Main oscillation clock (up to 16.25 MHz, maximum machine clock frequency: 8.125 MHz)
 - External clock (up to 32.5 MHz, maximum machine clock frequency: 16.25 MHz)
 - Main CR clock (4 MHz ±2%)
 - · Main CR PLL clock
 - The main CR PLL clock frequency becomes 8 MHz $\pm 2\%$ when the PLL multiplication rate is 2.
 - The main CR PLL clock frequency becomes 10 MHz $\pm 2\%$ when the PLL multiplication rate is 2.5.
 - The main CR PLL clock frequency becomes 12 MHz $\pm 2\%$ when the PLL multiplication rate is 3.
 - The main CR PLL clock frequency becomes 16 MHz $\pm 2\%$ when the PLL multiplication rate is 4.
- □ Selectable subclock source
 - · Suboscillation clock (32.768 kHz)
 - External clock (32.768 kHz)
 - Sub-CR clock (Typ: 100 kHz, Min: 50 kHz, Max: 150 kHz)

■ Timer

- □ 8/16-bit composite timer × 2 channels
- □ 8/16-bit PPG × 3 channels
- □ 16-bit PPG timer × 1 channel (can work independently or together with the multi-pulse generator)
- □ 16-bit reload timer × 1 channel (can work independently or together with the multi-pulse generator)
- ☐ Time-base timer × 1 channel
- □ Watch prescaler × 1 channel
- UART/SIO × 1 channel
 - Full duplex double buffer
 - Capable of clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer
- I²C bus interface × 1 channel
 - Built-in wake-up function
- Multi-pulse generator (MPG) (for DC motor control) × 1 channel
 - □ 16-bit reload timer × 1 channel
 - ☐ 16-bit PPG timer × 1 channel
 - □ Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function)
- **LIN-UART**
 - □ Full duplex double buffer

- Capable of clock asynchronous serial data transfer and clock synchronous serial data transfer
- External interrupt × 10 channels
 - □ Interrupt by edge detection (rising edge, falling edge, and both edges can be selected)
 - Can be used to wake up the device from different low power consumption (standby) modes
- 8/10-bit A/D converter × 8 channels
 - □ 8-bit or 10-bit resolution can be selected.
- Low power consumption (standby) modes
 - ☐ There are four standby modes as follows:
 - · Stop mode
 - · Sleep mode
 - · Watch mode
 - · Time-base timer mode
 - □ In standby mode, two further options can be selected: normal standby mode and deep standby mode.
- I/O port
 - MB95F632H/F633H/F634H/F636H (number of I/O ports: 28)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 3
 - ☐ MB95F632K/F633K/F634K/F636K (number of I/O ports: 29)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 4
- On-chip debug
 - □ 1-wire serial control
 - Serial writing supported (asynchronous mode)
- Hardware/software watchdog timer
 - Built-in hardware watchdog timer
 - Built-in software watchdog timer
- Power-on reset
 - A power-on reset is generated when the power is switched on.
- Low-voltage detection reset circuit (only available on MB95F632K/F633K/F634K/F636K)
 - Built-in low-voltage detection function (The combination of detection voltage and release voltage can be selected from four options.)
- Comparator
- Clock supervisor counter
 - ☐ Built-in clock supervisor counter
- Dual operation Flash memory
 - The program/erase operation and the read operation can be executed in different banks (upper bank/lower bank) simultaneously.
- Flash memory security function
 - Protects the content of the Flash memory.

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MB95630H Series



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1. Product Line-up

Part number		MDOFF622U	MD05E624U	MDOFESSEL	MDOEEGSSV	MDOEEGSSV	MDOEEG24V	MDOFF636V			
Parameter	WID95F63ZFI	MD32L033U	WD95F634F1	MIDSSLOSON	WD95F632K	MD32L033K	MB95F634K	MD33F036K			
Туре		Flash memory product									
Clock supervisor counter	It supervise	s the main	clock oscilla	ation and the	e subclock c	oscillation.					
Flash memory capacity	8 Kbyte	12 Kbyte	20 Kbyte	36 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte	36 Kbyte			
RAM capacity	256 bytes	512 bytes	1024 bytes	1024 bytes	256 bytes	512 bytes	1024 bytes	1024 bytes			
Power-on reset				Ye	es						
Low-voltage detection reset		Ν	lo			Y	es				
Reset input		Dedi	cated		S	elected thro	ough softwa	re			
CPU functions	Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (machine clock frequency = 16.25 MHz) Interrupt processing time : 0.6 µs (machine clock frequency = 16.25 MHz)										
General- purpose I/O	I/O portCMOS I/ON-ch ope		: 28 : 25 : 3		I/O portCMOS I/ON-ch ope		: 29 : 25 : 4				
Time-base timer	Interval tim	e: 0.256 ms	to 8.3 s (ex	cternal clock	frequency	= 4 MHz)					
Hardware/ software watchdog timer		cillation clo	ck at 10 MH	z: 105 ms (I as the sourc		ne software	watchdog ti	mer.			
Wild register	It can be us	sed to replac	ce 3 bytes c	of data.							
LIN-UART	It has a full both cloc enabled.	t can be used to replace 3 bytes of data. A wide range of communication speed can be selected by a dedicated reload timer. It has a full duplex double buffer. Both clock synchronous serial data transfer and clock asynchronous serial data transfer are enabled. The LIN function can be used as a LIN master or a LIN slave.									
8/10-bit	8 channels										
A/D converter	8-bit or 10-	oit resolutio	n can be se	lected.							
	2 channels										
 The timer can be configured as an "8-bit timer × 2 channels" or a "16-bit timer × 1 It has the following functions: interval timer function, PWC function, PWM function capture function. Count clock: it can be selected from internal clocks (seven types) and external contents. It can output square wave. 						on and input					

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Part number Parameter	MB95F632H	MB95F633H	MB95F634H	MB95F636H	MB95F632K	MB95F633K	MB95F634K	MB95F636K			
External interrupt		by edge dete				e, and both e		e selected.)			
()n_chin dahiid	1-wire ser	It can be used to wake up the device from different standby modes. 1-wire serial control It supports serial writing (asynchronous mode).									
	It has a fingeneratorIt uses theLSB-firstBoth cloce	Data transfer with UART/SIO is enabled. It has a full duplex double buffer, variable data length (5/6/7/8 bits), an internal baud rate generator and an error detection function. It uses the NRZ type transfer format. LSB-first data transfer and MSB-first data transfer are available to use. Both clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer are enabled.									
I ² C bus interface	 It has the tection fu 	Channel Master/slave transmission and reception It has the following functions: bus error function, arbitration function, transfer direction detection function, wake-up function, and functions of generating and detecting repeated START conditions.									
8/16-bit PPG						els" or a "16 clock sourc		1 channel".			
	The counIt support	ter operatin s external tr	g clock can igger start.		I from eight						
	 It can work independently or together with the multi-pulse generator. 1 channel Two clock modes and two counter operating modes are available to use. It can output square wave. Count clock: it can be selected from internal clocks (seven types) and external clocks. Two counter operating modes: reload mode and one-shot mode It can work independently or together with the multi-pulse generator. 										
III/IIIIti_niiica	16-bit reloEvent cou	16-bit PPG timer: 1 channel 16-bit reload timer operations: toggle output, one-shot output Event counter: 1 channel Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function)									
	Eight different time intervals can be selected.										
Comparator	1 channel										

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Part number Parameter		MB95F633H	MB95F634H	MB95	F636H	MB95F6	632K	MB95F63	33K	MB95F634K	MB95F636K
Flash memory	suspend/ • It has a flat • Flash sec	 It supports automatic programming (Embedded Algorithm), and program/erase/erase-suspend/erase-resume commands. It has a flag indicating the completion of the operation of Embedded Algorithm. Flash security feature for protecting the content of the Flash memory Number of program/erase cycles 1000 10000 									
	Data re	es		000 /ears		0000 years		100000 5 years			
	There are four standby modes as follows: • Stop mode • Sleep mode • Watch mode • Time-base timer mode In standby mode, two further options can be selected: normal standby mode and deep standby mode.										
Package	LQB032 PDS032 WNP032										

2. Packages And Corresponding Products

Part number Package		MB95F633H	MB95F634H	MB95F636H	MB95F632K	MB95F633K	MB95F634K	MB95F636K
LQB032	O	О	O	O	O	O	O	О
PDS032	О	О	О	О	О	О	О	О
WNP032	О	0	0	О	О	О	0	О

O: Available

3. Differences Among Products And Notes On Product Selection

Current consumption

When using the on-chip debug function, take account of the current consumption of Flash memory program/erase. For details of current consumption, see "Electrical Characteristics".

Package

For details of information on each package, see "Packages And Corresponding Products" and "Package Dimension".

· Operating voltage

The operating voltage varies, depending on whether the on-chip debug function is used or not. For details of operating voltage, see "Electrical Characteristics".

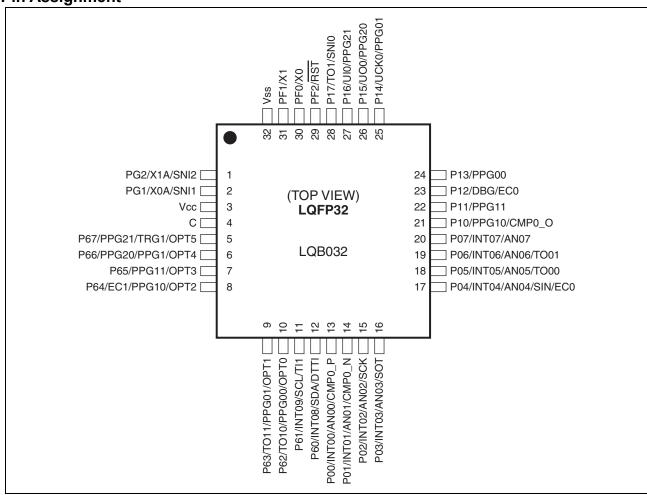
· On-chip debug function

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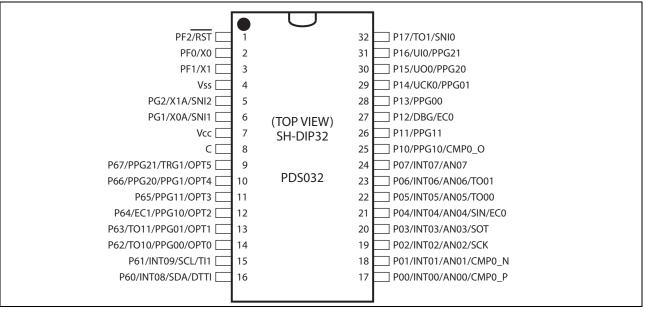
The on-chip debug function requires that Vcc, Vss and one serial wire be connected to an evaluation tool. For details of the connection method, refer to "CHAPTER 25 EXAMPLE OF SERIAL PROGRAMMING CONNECTION" in "New 8FX MB95630H Series Hardware Manual".

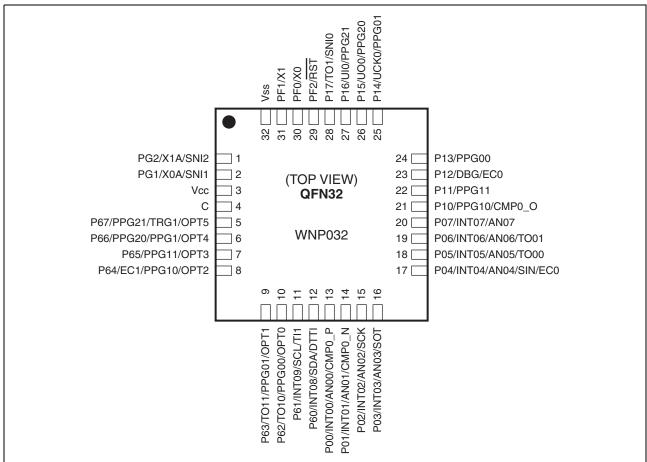
4. Pin Assignment



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5. Pin Functions

Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*⁵	PU*6
		PG2		General-purpose I/O port				
		X1A	_	Subclock I/O oscillation pin				
1	5	SNI2	С	Trigger input pin for the position detection function of the MPG waveform sequencer	Hysteresis	CMOS		О
		PG1		General-purpose I/O port				
		X0A		Subclock input oscillation pin				
2	6	SNI1	С	Trigger input pin for the position detection function of the MPG waveform sequencer	Hysteresis	CMOS		О
3	7	Vcc		Power supply pin	_	_		_
4	8	С	_	Decoupling capacitor connection pin	_	_	_	—
		P67		General-purpose I/O port High-current pin				
		PPG21	21	8/16-bit PPG ch. 2 output pin	Hysteresis			
5	9	TRG1	D	16-bit PPG timer ch. 1 trigger input pin		CMOS	_	О
		OPT5		MPG waveform sequencer output pin				
		P66		General-purpose I/O port High-current pin				
6	10	PPG20	D	8/16-bit PPG ch. 2 output pin	- Hysteresis	CMOS		О
	10	PPG1		16-bit PPG timer ch. 1 output pin	Tiyotoroolo	OWICO		
		OPT4		MPG waveform sequencer output pin				
		P65		General-purpose I/O port High-current pin				
7	11	PPG11	D	8/16-bit PPG ch. 1 output pin	Hysteresis	CMOS	_	О
		OPT3		MPG waveform sequencer output pin				
		P64		General-purpose I/O port High-current pin				
8	12	EC1	D	8/16-bit composite timer ch. 1 clock input pin	Hysteresis	CMOS	_	О
	0 12	PPG10		8/16-bit PPG ch. 1 output pin				
		OPT2		MPG waveform sequencer output pin				



Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*5	PU*6
		P63		General-purpose I/O port High-current pin				
9	13	TO11	D	8/16-bit composite timer ch. 1 output pin	Hysteresis	CMOS	_	0
		PPG01		8/16-bit PPG ch. 0 output pin				
		OPT1		MPG waveform sequencer output pin				
		P62		General-purpose I/O port High-current pin				
10	14	TO10	D	8/16-bit composite timer ch. 1 output pin	Hysteresis	CMOS		0
		PPG00		8/16-bit PPG ch. 0 output pin				
		OPT0		MPG waveform sequencer output pin				
		P61		General-purpose I/O port				
		INT09		External interrupt input pin				
11	15	SCL		I ² C bus interface ch. 0 clock I/O pin	CMOS	CMOS	О	_
		TI1		16-bit reload timer ch. 1 input pin				
		P60		General-purpose I/O port				
		INT08		External interrupt input pin	CMOS	CMOS		
12	16	SDA	I	I ² C bus interface ch. 0 data I/O pin			О	_
		DTTI		MPG waveform sequencer input pin				
		P00		General-purpose I/O port				
		INT00		External interrupt input pin				
13	17	AN00		8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	О
		CMP0_P		Comparator non-inverting analog input (positive input) pin				
		P01		General-purpose I/O port				
		INT01		External interrupt input pin				
14	18	AN01	Е	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	О
				Comparator inverting analog input (negative input) pin				



Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*⁵	PU*6
		P02		General-purpose I/O port				
		INT02		External interrupt input pin	I liveterecie/			
15	19	AN02	E	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	О
		SCK		LIN-UART clock I/O pin				
		P03		General-purpose I/O port				
		INT03		External interrupt input pin	I liveterecie/	,	_	
16	20	AN03	N03 E	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS		О
		SOT		LIN-UART data output pin				
		P04		General-purpose I/O port				
		INT04		External interrupt input pin		CMOS		
17	21	AN04	F	8/10-bit A/D converter analog input pin	CMOS/ analog		_	О
		SIN		LIN-UART data input pin				
		EC0		8/16-bit composite timer ch. 0 clock input pin				
		P05		General-purpose I/O port	Hysteresis/ analog	CMOS	_	
		INT05		External interrupt input pin				
18	22	AN05	Е	8/10-bit A/D converter analog input pin				О
		TO00		8/16-bit composite timer ch. 0 output pin				
		P06		General-purpose I/O port				
		INT06		External interrupt input pin				
19	23	AN06	Е	8/10-bit A/D converter analog input pin	Hysteresis/ analog	CMOS	_	О
		TO01		8/16-bit composite timer ch. 0 output pin				
		P07		General-purpose I/O port				
20	24	INT07		External interrupt input pin	Hysteresis/	CMOS		О
20	<u> </u>	AN07	_	8/10-bit A/D converter analog input pin	analog	Sivioo		
		P10		General-purpose I/O port				
21	25	PPG10	G	8/16-bit PPG ch. 1 output pin	Hysteresis	CMOS	_	О
		CMP0_O		Comparator digital output pin	1			



Pin	no.		I/O			I/O type		
LQFP32*1, QFN32*2	SH-DIP32*3	Pin name	circuit type*4	Function	Input	Output	OD*5	PU*6
22	26	P11	G	General-purpose I/O port	Hysteresis	CMOS		О
22	20	PPG11)	8/16-bit PPG ch. 1 output pin	Trysteresis	CIVIOS		O
		P12		General-purpose I/O port				
23	27	DBG	Н	DBG input pin	Hysteresis	CMOS	О	
		EC0		8/16-bit composite timer ch. 0 clock input pin	.,,			
24	28	P13	G	General-purpose I/O port	Hysteresis	CMOS		0
24	20	PPG00	G	8/16-bit PPG ch. 0 output pin	пузістезіз	CIVIOS		U
		P14		General-purpose I/O port				
25	29	UCK0	G	UART/SIO ch. 0 clock I/O pin	Hysteresis	CMOS	_	О
		PPG01		8/16-bit PPG ch. 0 output pin]			
		P15		General-purpose I/O port				
26	30	UO0	G	UART/SIO ch. 0 data output pin	Hysteresis	CMOS	_	О
		PPG20		8/16-bit PPG ch. 2 output pin				
		P16		General-purpose I/O port				
27	31	UI0	J	UART/SIO ch. 0 data input pin	CMOS	CMOS	_	О
		PPG21		8/16-bit PPG ch. 2 output pin				
	32	P17		General-purpose I/O port				
28		TO1	G	16-bit reload timer ch. 1 output pin	Hysteresis	CMOS	_	О
20	32	SNI0		Trigger input pin for the position detection function of the MPG waveform sequencer	11,900.00.0	ooo		0
		PF2		General-purpose I/O port				
29	1	RST	Α	Reset pin Dedicated reset pin on MB95F632H/F633H/F634H/ F636H	Hysteresis	CMOS	О	
30	2	PF0	P	General-purpose I/O port	Hysteresis	CMOS		
30		X0 B		Main clock input oscillation pin	TIYSICICSIS	CMOS		
31	3	PF1	В	General-purpose I/O port	Hysteresis	CMOS		
JI	ى 	X1		Main clock I/O oscillation pin	i iyəleresis	CIVIOS		
32	4	Vss	_	Power supply pin (GND)	_	_		_

O: Available

*4: For the I/O circuit types, see "I/O Circuit Type".

*1: LQB032 *2: WNP032

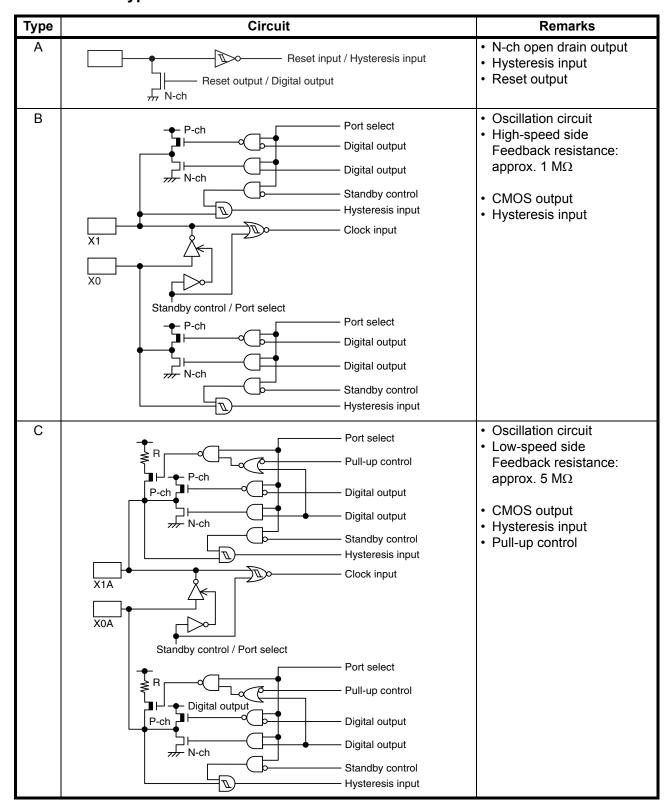
*3: PDS032

^{*5:} N-ch open drain

^{*6:} Pull-up



6. I/O Circuit Type





Type	Circuit		Remarks
D	₹R C	— Pull-up control	CMOS outputHysteresis inputPull-up control
	P-ch	— Digital output	High current output
	N-ch	— Digital output	
	<i>///</i> Non	Standby control	
		— Hysteresis input	
E	₹R F	— Pull-up control	CMOS outputHysteresis inputPull-up control
	P-ch P-ch	— Digital output	Analog input
	N-ch	— Digital output	
	<u></u>	— Analog input	
		A/D control Standby control Hysteresis input	
F	₹R ₹R	— Pull-up control	CMOS output CMOS input Pull-up control
	P-ch P-ch	— Digital output	Analog input
	N-ch	— Digital output	
	<u> </u>	— Analog input	
		— A/D control — Standby control — CMOS input	
G	₹R C	— Pull-up control	CMOS outputHysteresis inputPull-up control
	P-ch P-ch	— Digital output	
		— Digital output	
	N-ch	— Standby control	
		— Hysteresis input	
Н		—— Standby control	N-ch open drain outputHysteresis input
		Hysteresis input	- Hysteresis IIIput
	Digital output N-ch		



Type	Circuit	Remarks
I	Digital output N-ch Standby control CMOS input	N-ch open drain outputCMOS input
J	Pull-up control	CMOS output CMOS input Pull-up control
	P-ch Digital output	
	Digital output	
	Standby control CMOS input	

7. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

7.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

• Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

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(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.

Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (2) Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

• Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

• Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

7.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually

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causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

• Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
 - When you open Dry Package that recommends humidity 40% to 70% relative humidity.
- (3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

- (1) Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
- (2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 M Ω).
 - Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
- (4) Ground all fixtures and instruments, or protect with anti-static measures.
- (5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

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7.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

8. Notes On Device Handling

Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.

In a CMOS IC, if a voltage higher than Vcc or a voltage lower than Vss is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in "18.1 Absolute Maximum Ratings" of "Electrical Characteristics" is applied to the Vcc pin or the Vss pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

Stabilizing supply voltage

Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the Vcc power supply voltage.

As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in Vcc ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard Vcc value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

· Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

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9. Pin Connection

· Treatment of unused pins

If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latchups. Always pull up or pull down an unused input pin through a resistor of at least $2 \text{ k}\Omega$. Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

· Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the Vcc pin and the Vss pin to the power supply and ground outside the device. In addition, connect the current supply source to the Vcc pin and the Vss pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 μF as a bypass capacitor between the Vcc pin and the Vss pin at a location close to this device.

DBG pin

Connect the DBG pin to an external pull-up resistor of 2 k Ω or above.

After power-on, ensure that the DBG pin does not stay at "L" level until the reset output is released.

The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

• RST pin

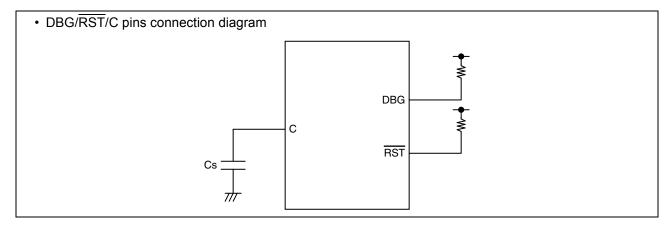
Connect the $\overline{\mathsf{RST}}$ pin to an external pull-up resistor of 2 k Ω or above.

To prevent the device from unintentionally entering the reset mode due to noise, minimize the interconnection length between a pull-up resistor and the RST pin and that between a pull-up resistor and the Vcc pin when designing the layout of the printed circuit board.

The PF2/RST pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/RST pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general-purpose I/O function can be selected by the RSTEN bit in the SYSC register.

• C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs. For the connection to a decoupling capacitor Cs, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and Cs and the distance between Cs and the Vss pin when designing the layout of a printed circuit board.



· Note on serial communication

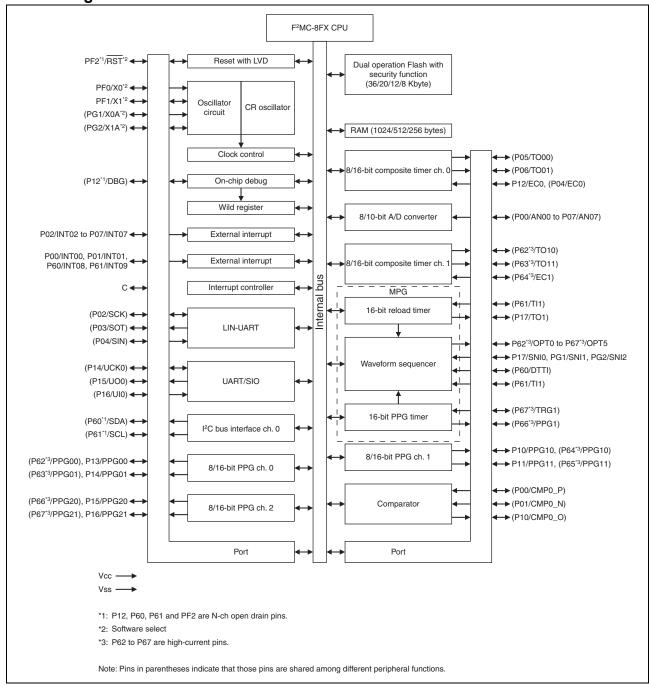
In serial communication, reception of wrong data may occur due to noise or other causes. Therefore, design a printed

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circuit board to prevent noise from occurring. Taking account of the reception of wrong data, take measures such as adding a checksum to the end of data in order to detect errors. If an error is detected, retransmit the data.

10. Block Diagram





11. CPU Core

Memory space

The memory space of the MB95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the MB95630H Series are shown below.

Memory maps

MB95F632H/F632K		MB95F633H/F633K		MB95F634H/F634K		MB95F636H/F636K
I/O area Access prohibited RAM 256 bytes Registers	0x0000 0x0080 0x0090 0x0100 0x0200 0x0290	I/O area Access prohibited RAM 512 bytes Registers	0x0000 0x0080 0x0090 0x0100 0x0200	I/O area Access prohibited RAM 1024 bytes Registers	0x0000 0x0080 0x0090 0x0100 0x0200	I/O area Access prohibited RAM 1024 bytes Registers
Access prohibited		Access prohibited	0x0490 -	Access prohibited	- 0x0490 -	Access prohibited
Extended I/O area	0x0F80	Extended I/O area	0x0F80	Extended I/O area	0x0F80	Extended I/O area
Flash memory 4 Kbyte		Flash memory 4 Kbyte		Flash memory 4 Kbyte		Flash memory 4 Kbyte
		Access prohibited		Access prohibited	0x8000 -	Access prohibited
Access prohibited			0xC000 -			Flash memory 32 Kbyte
	. 5000		-	Flash memory 16 Kbyte		
	0xE000 -	Flash memory 8 Kbyte				
	I/O area Access prohibited RAM 256 bytes Registers Access prohibited Extended I/O area Flash memory 4 Kbyte	No area	Access prohibited RaM 256 bytes Registers Access prohibited Access prohibited	VO area	I/O area	1/O area

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12. Memory Space

The memory space of the MB95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas for specific applications such as general-purpose registers and a vector table.

- I/O area (addresses: 0x0000 to 0x007F)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the I/O area forms part of the memory space, it can be accessed in the same way as the memory. It can also be accessed at high-speed by using direct addressing instructions.
- Extended I/O area (addresses: 0x0F80 to 0x0FFF)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the extended I/O area forms part of the memory space, it can be accessed in the same way as the memory.

Data area

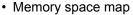
- Static RAM is incorporated in the data area as the internal data area.
- The internal RAM size varies according to product.
- The RAM area from 0x0090 to 0x00FF can be accessed at high-speed by using direct addressing instructions.
- In MB95F636H/F636K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F634H/F634K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F633H/F633K, the area from 0x0090 to 0x028F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F632H/F632K, the area from 0x0090 to 0x018F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F633H/F633K/F634H/F634K/F636H/F636K, the area from 0x0100 to 0x01FF can be used as a general-purpose register area.
- In MB95F632H/F632K, the area from 0x0100 to 0x018F can be used as a general-purpose register area.

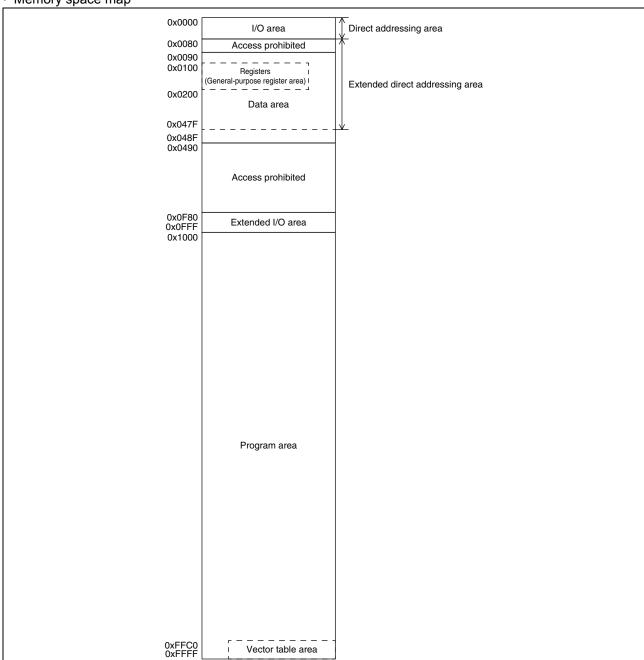
Program area

- · The Flash memory is incorporated in the program area as the internal program area.
- The Flash memory size varies according to product.
- The area from 0xFFC0 to 0xFFFF is used as the vector table.
- The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register.

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13. Areas For Specific Applications

The general-purpose register area and vector table area are used for the specific applications.

- General-purpose register area (Addresses: 0x0100 to 0x01FF*1)
 - This area contains the auxiliary registers used for 8-bit arithmetic operations, transfer, etc.
 - As this area forms part of the RAM area, it can also be used as conventional RAM.
 - When the area is used as general-purpose registers, general-purpose register addressing enables high-speed access with short instructions.
- Non-volatile register data area (Addresses: 0xFFBB to 0xFFBF)
 - The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register. For details, refer to "CHAPTER 26 NON-VOLATILE REGISTER (NVR) INTERFACE" in "New 8FX MB95630H Series Hardware Manual".
- Vector table area (Addresses: 0xFFC0 to 0xFFFF)
 - This area is used as the vector table for vector call instructions (CALLV), interrupts, and resets.
 - The top of the Flash memory area is allocated to the vector table area. The start address of a service routine is set to an address in the vector table in the form of data.

"Interrupt Source Table" lists the vector table addresses corresponding to vector call instructions, interrupts, and resets.

For details, refer to "CHAPTER 4 RESET", "CHAPTER 5 INTERRUPTS" and "A.2 Special Instruction ■ Special Instruction ■ Special Instruction ■ CALLV #vct" in "New 8FX MB95630H Series Hardware Manual".

Direct bank pointer and access area

Direct bank pointer (DP[2:0])	Operand-specified dir	Access area
0bXXX (It does not affect mapping.)	0x0000 to 0x007F	0x0000 to 0x007F
0b000 (Initial value)	0x0090 to 0x00FF	0x0090 to 0x00FF
0b001		0x0100 to 0x017F
0b010	_	0x0180 to 0x01FF*1
0b011		0x0200 to 0x027F
0b100	0x0080 to 0x00FF	0x0280 to 0x02FF*2
0b101		0x0300 to 0x037F
0b110	_	0x0380 to 0x03FF
0b111		0x0400 to 0x047F

^{*1:} Due to the memory size limit, the available access area is up to "0x018F" in MB95F632H/F632K.

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^{*2:} Due to the memory size limit, the available access area is up to "0x028F" in MB95F633H/F633K.



14. I/O Map

Address	Register abbreviation	Register name		Initial value
0x0000	PDR0	Port 0 data register	R/W	0b00000000
0x0001	DDR0	Port 0 direction register		0b00000000
0x0002	PDR1	Port 1 data register		0b00000000
0x0003	DDR1	Port 1 direction register	R/W	0b00000000
0x0004	_	(Disabled)		_
0x0005	WATR	Oscillation stabilization wait time setting register	R/W	0b11111111
0x0006	PLLC	PLL control register	R/W	0b000X0000
0x0007	SYCC	System clock control register	R/W	0bXXX11011
0x0008	STBC	Standby control register	R/W	0b00000000
0x0009	RSRR	Reset source register	R/W	0b000XXXXX
0x000A	TBTC	Time-base timer control register	R/W	0b00000000
0x000B	WPCR	Watch prescaler control register	R/W	0b00000000
0x000C	WDTC	Watchdog timer control register	R/W	0b00XX0000
0x000D	SYCC2	System clock control register 2	R/W	0bXXXX0011
0x000E	STBC2	Standby control register 2	R/W	0b00000000
0x000F				
to 0x0015	_	(Disabled)	_	_
0x0015	PDR6	Dort 6 data register	R/W	0b00000000
0x0016	DDR6	Port 6 data register Port 6 direction register		0b00000000
0x0017	DDR0	1 or o unection register		000000000
to	_	(Disabled)	_	_
0x0027		(2222)		
0x0028	PDRF	Port F data register	R/W	0b00000000
0x0029	DDRF	Port F direction register	R/W	0b00000000
0x002A	PDRG	Port G data register	R/W	0b00000000
0x002B	DDRG	Port G direction register	R/W	0b00000000
0x002C	PUL0	Port 0 pull-up register	R/W	0b00000000
0x002D	PUL1	Port 1 pull-up register	R/W	0b00000000
0x002E				
to	_	(Disabled)	-	_
0x0032	DULG	Dort Coull up as sister	DAY	050000000
0x0033	PUL6	Port 6 pull-up register	R/W	0b00000000
0x0034	— —	(Disabled)		— 0h0000000
0x0035	PULG	Port G pull-up register	R/W	0b00000000
0x0036	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0b00000000



Address	Register abbreviation	Register name	R/W	Initial value
0x0037	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0b00000000
0x0038	T11CR1	8/16-bit composite timer 11 status control register 1	R/W	0b00000000
0x0039	T10CR1	8/16-bit composite timer 10 status control register 1		0b00000000
0x003A	PC01	8/16-bit PPG timer 01 control register		0b00000000
0x003B	PC00	8/16-bit PPG timer 00 control register		0b00000000
0x003C	PC11	8/16-bit PPG timer 11 control register	R/W	0b00000000
0x003D	PC10	8/16-bit PPG timer 10 control register	R/W	0b00000000
0x003E	PC21	8/16-bit PPG timer 21 control register	R/W	0b00000000
0x003F	PC20	8/16-bit PPG timer 20 control register	R/W	0b00000000
0x0040	TMCSRH1	16-bit reload timer control status register (upper)	R/W	0b00000000
0x0041	TMCSRL1	16-bit reload timer control status register (lower)	R/W	0b00000000
0x0042	CMR0C	Comparator control register	R/W	0b00000101
0x0043	_	(Disabled)	_	_
0x0044	PCNTH1	16-bit PPG status control register (upper)	R/W	0b00000000
0x0045	PCNTL1	16-bit PPG status control register (lower)	R/W	0b00000000
0x0046, 0x0047	_	(Disabled)	_	_
0x0048	EIC00	External interrupt circuit control register ch. 0/ch. 1	R/W	0b00000000
0x0049	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	0b00000000
0x004A	EIC20	External interrupt circuit control register ch. 4/ch. 5		0b00000000
0x004B	EIC30	External interrupt circuit control register ch. 6/ch. 7		0b00000000
0x004C	EIC01	External interrupt circuit control register ch. 8/ch. 9	R/W	0b00000000
0x004D	_	(Disabled)	_	
0x004E	LVDR	LVD reset voltage selection ID register	R/W	0b00000000
0x004F	_	(Disabled)	_	_
0x0050	SCR	LIN-UART serial control register	R/W	0b00000000
0x0051	SMR	LIN-UART serial mode register	R/W	0b00000000
0x0052	SSR	LIN-UART serial status register	R/W	0b00001000
0,0053	RDR	LIN-UART receive data register	R/W	0b00000000
0x0053	TDR	LIN-UART transmit data register		000000000
0x0054	ESCR	LIN-UART extended status control register	R/W	0b00000100
0x0055	ECCR	LIN-UART extended communication control register	R/W	0b000000XX
0x0056	SMC10	UART/SIO serial mode control register 1	R/W	0b00000000
0x0057	SMC20	UART/SIO serial mode control register 2	R/W	0b00100000
0x0058	SSR0	UART/SIO serial status and data register		0b00000001
0x0059	TDR0	UART/SIO serial output data register	R/W	0b00000000



Address	Register abbreviation	Register name		Initial value
0x005A	RDR0	UART/SIO serial input data register	R	0b00000000
0x005B to 0x005F	_	(Disabled)	_	
0x0060	IBCR00	I ² C bus control register 0 ch. 0	R/W	0b00000000
0x0061	IBCR10	I ² C bus control register 1 ch. 0	R/W	0b00000000
0x0062	IBSR0	I ² C bus status register ch. 0	R/W	0b00000000
0x0063	IDDR0	I ² C data register ch. 0	R/W	0b00000000
0x0064	IAAR0	I ² C address register ch. 0	R/W	0b00000000
0x0065	ICCR0	I ² C clock control register ch. 0	R/W	0b00000000
0x0066	OPCUR	16-bit MPG output control register (upper)	R/W	0b00000000
0x0067	OPCLR	16-bit MPG output control register (lower)	R/W	0b00000000
0x0068	IPCUR	16-bit MPG input control register (upper)	R/W	0b00000000
0x0069	IPCLR	16-bit MPG input control register (lower)	R/W	0b00000000
0x006A	NCCR	16-bit MPG noise cancellation control register	R/W	0b00000000
0x006B	TCSR	16-bit MPG timer control status register	R/W	0b00000000
0x006C	ADC1	8/10-bit A/D converter control register 1	R/W	0b00000000
0x006D	ADC2	8/10-bit A/D converter control register 2		0b00000000
0x006E	ADDH	8/10-bit A/D converter data register (upper)		0b00000000
0x006F	ADDL	8/10-bit A/D converter data register (lower)		0b00000000
0x0070	_	(Disabled)		_
0x0071	FSR2	Flash memory status register 2		0b00000000
0x0072	FSR	Flash memory status register	R/W	0b000X0000
0x0073	SWRE0	Flash memory sector write control register 0	R/W	0b00000000
0x0074	FSR3	Flash memory status register 3	R	0b000XXXXX
0x0075	FSR4	Flash memory status register 4	R/W	0b00000000
0x0076	WREN	Wild register address compare enable register	R/W	0b00000000
0x0077	WROR	Wild register data test setting register	R/W	0b00000000
0x0078	_	Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	_
0x0079	ILR0	Interrupt level setting register 0	R/W	0b11111111
0x007A	ILR1	Interrupt level setting register 1	R/W	0b11111111
0x007B	ILR2	Interrupt level setting register 2	R/W	0b11111111
0x007C	ILR3	Interrupt level setting register 3	R/W	0b11111111
0x007D	ILR4	Interrupt level setting register 4	R/W	0b11111111
0x007E	ILR5	Interrupt level setting register 5	R/W	0b11111111
0x007F	_	(Disabled)	<u> </u>	_



Address	Register abbreviation	Register name	R/W	Initial value
0x0F80	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0b00000000
0x0F81	WRARL0	Wild register address setting register (lower) ch. 0		0b00000000
0x0F82	WRDR0	Wild register data setting register ch. 0		0b00000000
0x0F83	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0b00000000
0x0F84	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0b00000000
0x0F85	WRDR1	Wild register data setting register ch. 1	R/W	0b00000000
0x0F86	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0b00000000
0x0F87	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0b00000000
0x0F88	WRDR2	Wild register data setting register ch. 2	R/W	0b00000000
0x0F89 to 0x0F91	_	(Disabled)	_	_
0x0F92	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0b00000000
0x0F93	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0b00000000
0x0F94	T01DR	8/16-bit composite timer 01 data register	R/W	0b00000000
0x0F95	T00DR	8/16-bit composite timer 00 data register	R/W	0b00000000
0x0F96	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0b00000000
0x0F97	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	0b00000000
0x0F98	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	0b00000000
0x0F99	T11DR	8/16-bit composite timer 11 data register		0b00000000
0x0F9A	T10DR	8/16-bit composite timer 10 data register	R/W	0b00000000
0x0F9B	TMCR1	8/16-bit composite timer 10/11 timer mode control register	R/W	0b00000000
0x0F9C	PPS01	8/16-bit PPG01 cycle setting buffer register	R/W	0b11111111
0x0F9D	PPS00	8/16-bit PPG00 cycle setting buffer register	R/W	0b11111111
0x0F9E	PDS01	8/16-bit PPG01 duty setting buffer register	R/W	0b11111111
0x0F9F	PDS00	8/16-bit PPG00 duty setting buffer register	R/W	0b11111111
0x0FA0	PPS11	8/16-bit PPG11 cycle setting buffer register	R/W	0b11111111
0x0FA1	PPS10	8/16-bit PPG10 cycle setting buffer register	R/W	0b11111111
0x0FA2	PDS11	8/16-bit PPG11 duty setting buffer register	R/W	0b11111111
0x0FA3	PDS10	8/16-bit PPG10 duty setting buffer register	R/W	0b11111111
0x0FA4	PPGS	8/16-bit PPG start register	R/W	0b00000000
0x0FA5	REVC	8/16-bit PPG output inversion register	R/W	0b00000000
0x0FA6	PPS21	8/16-bit PPG21 cycle setting buffer register	R/W	0b11111111
0x0FA7	PPS20	8/16-bit PPG20 cycle setting buffer register	R/W	0b11111111



Address	Register abbreviation	Register name		Initial value
0.0540	TMRH1	16-bit reload timer timer register (upper)	DAA	050000000
0x0FA8	TMRLRH1	16-bit reload timer reload register (upper)	R/W	0b00000000
0،،۵۳۸۵	TMRL1	16-bit reload timer timer register (lower)		050000000
0x0FA9	TMRLRL1	16-bit reload timer reload register (lower)	H/VV	0b00000000
0x0FAA	PDS21	8/16-bit PPG21 duty setting buffer register		0b11111111
0x0FAB	PDS20	8/16-bit PPG20 duty setting buffer register	R/W	0b11111111
0x0FAC				
to 0x0FAF	_	(Disabled)	-	_
0x0FB0	PDCRH1	16-bit PPG downcounter register (upper)	R	0b00000000
0x0FB0	PDCRL1	16-bit PPG downcounter register (lower)	R	0b00000000
0x0FB1	PCSRH1	16-bit PPG cycle setting buffer register (upper)	R/W	0b11111111
0x0FB3	PCSRL1	16-bit PPG cycle setting buffer register (lower)	R/W	0b11111111 0b111111111
0x0FB4	PDUTH1	3 3 3 7	R/W	0b11111111 0b111111111
0x0FB5		16-bit PPG duty setting buffer register (upper)	_	
	PDUTL1	16-bit PPG duty setting buffer register (lower)	R/W	0b11111111
0x0FB6 to	_	(Disabled)	_	_
0x0FBB		(Bloadioa)		
0x0FBC	BGR1	LIN-UART baud rate generator register 1	R/W	0b00000000
0x0FBD	BGR0	LIN-UART baud rate generator register 0		0b00000000
0x0FBE	PSSR0	UART/SIO dedicated baud rate generator prescaler select register		0b00000000
0x0FBF	BRSR0	UART/SIO dedicated baud rate generator baud rate setting register	R/W	0b00000000
0x0FC0 to		(Disabled)	_	_
0x0FC2				
0x0FC3	AIDRL	A/D input disable register (lower)	R/W	0b00000000
0x0FC4	OPDBRH0	16-bit MPG output data buffer register (upper) ch. 0	R/W	0b00000000
0x0FC5	OPDBRL0	16-bit MPG output data buffer register (lower) ch. 0	R/W	0b00000000
0x0FC6	OPDBRH1	16-bit MPG output data buffer register (upper) ch. 1	R/W	0b00000000
0x0FC7	OPDBRL1	16-bit MPG output data buffer register (lower) ch. 1	R/W	0b00000000
0x0FC8	OPDBRH2	16-bit MPG output data buffer register (upper) ch. 2	R/W	0b00000000
0x0FC9	OPDBRL2	16-bit MPG output data buffer register (lower) ch. 2	R/W	0b00000000
0x0FCA	OPDBRH3	16-bit MPG output data buffer register (upper) ch. 3	R/W	0b00000000
0x0FCB	OPDBRL3	16-bit MPG output data buffer register (lower) ch. 3	R/W	0b00000000
0x0FCC	OPDBRH4	16-bit MPG output data buffer register (upper) ch. 4	R/W	0b00000000
0x0FCD	OPDBRL4	16-bit MPG output data buffer register (lower) ch. 4	R/W	0b00000000



Address	Register abbreviation	Register name	R/W	Initial value
0x0FCE	OPDBRH5	16-bit MPG output data buffer register (upper) ch. 5	R/W	0b00000000
0x0FCF	OPDBRL5	16-bit MPG output data buffer register (lower) ch. 5		0b00000000
0x0FD0	OPDBRH6	16-bit MPG output data buffer register (upper) ch. 6		0b00000000
0x0FD1	OPDBRL6	16-bit MPG output data buffer register (lower) ch. 6	R/W	0b00000000
0x0FD2	OPDBRH7	16-bit MPG output data buffer register (upper) ch. 7	R/W	0b00000000
0x0FD3	OPDBRL7	16-bit MPG output data buffer register (lower) ch. 7	R/W	0b00000000
0x0FD4	OPDBRH8	16-bit MPG output data buffer register (upper) ch. 8	R/W	0b00000000
0x0FD5	OPDBRL8	16-bit MPG output data buffer register (lower) ch. 8	R/W	0b00000000
0x0FD6	OPDBRH9	16-bit MPG output data buffer register (upper) ch. 9	R/W	0b00000000
0x0FD7	OPDBRL9	16-bit MPG output data buffer register (lower) ch. 9	R/W	0b00000000
0x0FD8	OPDBRHA	16-bit MPG output data buffer register (upper) ch. A	R/W	0b00000000
0x0FD9	OPDBRLA	16-bit MPG output data buffer register (lower) ch. A	R/W	0b00000000
0x0FDA	OPDBRHB	16-bit MPG output data buffer register (upper) ch. B	R/W	0b00000000
0x0FDB	OPDBRLB	16-bit MPG output data buffer register (lower) ch. B	R/W	0b00000000
0x0FDC	OPDUR	16-bit MPG output data register (upper)	R	0b0000XXXX
0x0FDD	OPDLR	16-bit MPG output data register (lower)	R	0bXXXXXXXX
0x0FDE	CPCUR	16-bit MPG compare clear register (upper)	R/W	0bXXXXXXXX
0x0FDF	CPCLR	16-bit MPG compare clear register (lower)		0bXXXXXXXX
0x0FE0, 0x0FE1	_	(Disabled)		_
0x0FE2	TMBUR	16-bit MPG timer buffer register (upper)	R	0bXXXXXXXX
0x0FE3	TMBLR	16-bit MPG timer buffer register (lower)		0bXXXXXXXX
0x0FE4	CRTH	Main CR clock trimming register (upper)		0b000XXXXX
0x0FE5	CRTL	Main CR clock trimming register (lower)	R/W	0b000XXXXX
0x0FE6	_	(Disabled)	_	_
0x0FE7	CRTDA	Main CR clock temperature dependent adjustment register	R/W	0b000XXXXX
0x0FE8	SYSC	System configuration register	R/W	0b11000011
0x0FE9	CMCR	Clock monitoring control register	R/W	0b00000000
0x0FEA	CMDR	Clock monitoring data register	R	0b00000000
0x0FEB	WDTH	Watchdog timer selection ID register (upper)	R	0bXXXXXXXX
0x0FEC	WDTL	Watchdog timer selection ID register (lower)	R	0bXXXXXXXX
0x0FED, 0x0FEE	_	(Disabled)		_
0x0FEF	WICR	Interrupt pin selection circuit control register	R/W	0b01000000
0x0FF0 to 0x0FFF	_	(Disabled)	-	_



R/W access symbols

R/W : Readable/Writable

R : Read onlyInitial value symbols

The initial value of this bit is "0".The initial value of this bit is "1".

X : The initial value of this bit is undefined.

Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.

15. I/O Ports

· List of port registers

Register name		Read/Write	Initial value
Port 0 data register	PDR0	R, RM/W	0b0000000
Port 0 direction register	DDR0	R/W	0b0000000
Port 1 data register	PDR1	R, RM/W	0b0000000
Port 1 direction register	DDR1	R/W	0b0000000
Port 6 data register	PDR6	R, RM/W	0b0000000
Port 6 direction register	DDR6	R/W	0b0000000
Port F data register	PDRF	R, RM/W	0b0000000
Port F direction register	DDRF	R/W	0b0000000
Port G data register	PDRG	R, RM/W	0b0000000
Port G direction register	DDRG	R/W	0b0000000
Port 0 pull-up register	PUL0	R/W	0b0000000
Port 1 pull-up register	PUL1	R/W	0b0000000
Port 6 pull-up register	PUL6	R/W	0b00000000
Port G pull-up register	PULG	R/W	0b00000000
A/D input disable register (lower)	AIDRL	R/W	0b0000000

R/W : Readable/writable (The read value is the same as the write value.)

R, RM/W : Readable/writable (The read value is different from the write value. The write value is read by the read-modify-write (RMW) type of instruction.)



15.1 Port 0

Port 0 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.1.1 Port 0 configuration

Port 0 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 0 data register (PDR0)
- Port 0 direction register (DDR0)
- Port 0 pull-up register (PUL0)
- A/D input disable register (lower) (AIDRL)

15.1.2 Block diagrams of port 0

P00/INT00/AN00/CMP0_P pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT00)
- 8/10-bit A/D converter analog input pin (AN00)
- Comparator non-inverting analog input (positive input) pin (CMP0 P)

• P01/INT01/AN01/CMP0 N pin

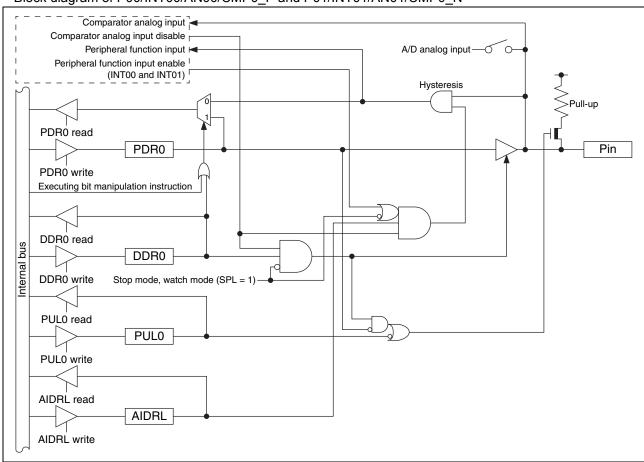
This pin has the following peripheral functions:

- External interrupt circuit input pin (INT01)
- 8/10-bit A/D converter analog input pin (AN01)
- Comparator inverting analog input (negative input) pin (CMP0 N)

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Block diagram of P00/INT00/AN00/CMP0_P and P01/INT01/AN01/CMP0_N





• P02/INT02/AN02/SCK pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT02)
- 8/10-bit A/D converter analog input pin (AN02)
- LIN-UART clock I/O pin (SCK)

• P03/INT03/AN03/SOT pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT03)
- 8/10-bit A/D converter analog input pin (AN03)
- LIN-UART data output pin (SOT)

• P05/INT05/AN05/TO00 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT05)
- 8/10-bit A/D converter analog input pin (AN05)
- 8/16-bit composite timer ch. 0 output pin (TO00)

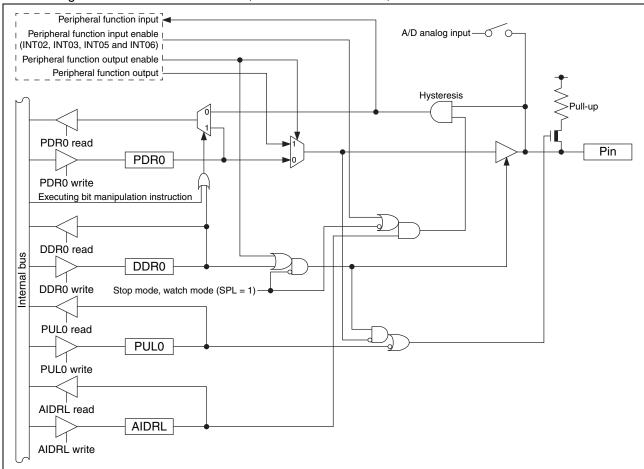
• P06/INT06/AN06/TO01 pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT06)
- 8/10-bit A/D converter analog input pin (AN06)
- 8/16-bit composite timer ch. 0 output pin (TO01)



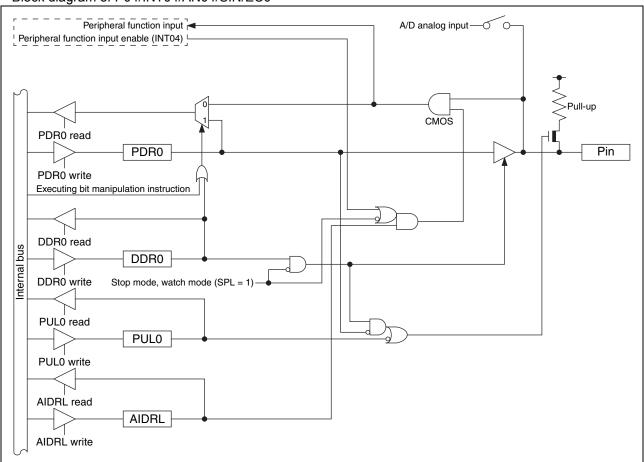
Block diagram of P02/INT02/AN02/SCK, P03/INT03/AN03/SOT, P05/INT05/AN05/TO00 and P06/INT06/AN06/TO01





- P04/INT04/AN04/SIN/EC0 pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT04)
 - 8/10-bit A/D converter analog input pin (AN04)
 - LIN-UART data input pin (SIN)
 - 8/16-bit composite timer ch. 0 clock input pin (EC0)

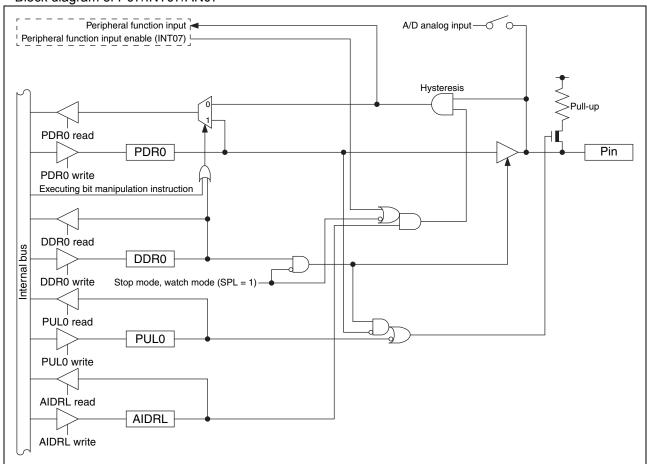
Block diagram of P04/INT04/AN04/SIN/EC0





- P07/INT07/AN07 pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT07)
 - 8/10-bit A/D converter analog input pin (AN07)

Block diagram of P07/INT07/AN07





15.1.3 Port 0 registers

Port 0 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write					
PDR0	0	Pin state is "L" level.	PDR0 value is "0".	As output port, outputs "L" level.					
	1	Pin state is "H" level.	PDR0 value is "1".	As output port, outputs "H" level.					
DDR0	0	Port input enabled							
DDRO	1		Port output enabled						
PUL0	0		Pull-up disabled						
FOLO	1	Pull-up enabled							
AIDRL	0		Analog input enabled						
AIDINE	1		Port input enabled	d					

Correspondence between registers and pins for port 0

		Correspondence between related register bits and pins									
Pin name	P07	P06	P05	P04	P03	P02	P01	P00			
PDR0											
DDR0	h:17	h:tC	b:45	b:#4	h:40	h:#0	h:44	h:+O			
PUL0	bit7	DILO	bit6 bit5	bit4	bit3	bit2	bit1	bit0			
AIDRL											

15.1.4 Port 0 operations

- · Operation as an output port
 - A pin becomes an output port if the bit in the DDR0 register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR0 register to external pins.
 - If data is written to the PDR0 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR0 register returns the PDR0 register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDR0 register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When using a pin shared with the analog input function as an input port, set the corresponding bit in the A/D input disable register (lower) (AIDRL) to "1".
 - If data is written to the PDR0 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR0 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR0 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR0 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.

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- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR0 register corresponding to the input pin of a peripheral function to "0".
 - When using a pin shared with the analog input function as another peripheral function input pin, configure it as an input port by setting the bit in the AIDRL register corresponding to that pin to "1".
 - Reading the PDR0 register returns the pin value, regardless of whether the peripheral function uses that pin as its
 input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0
 register value is returned.

Operation at reset

If the CPU is reset, all bits in the DDR0 register are initialized to "0" and port input is enabled. As for a pin shared with analog input, its port input is disabled because the AIDRL register is initialized to "0".

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR0 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input is enabled for the external interrupt (INT00 to INT07), the input is enabled and not blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- · Operation as an analog input pin
 - Set the bit in the DDR0 register bit corresponding to the analog input pin to "0" and the bit corresponding to that pin in the AIDRL register to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions. In addition, set the corresponding bit in the PUL0 register to "0".
- Operation as an external interrupt input pin
 - Set the bit in the DDR0 register corresponding to the external interrupt input pin to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - The pin value is always input to the external interrupt circuit. When using a pin for a function other than the interrupt, disable the external interrupt function corresponding to that pin.
- Operation of the pull-up register

Setting the bit in the PUL0 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL0 register.

- Operation as a comparator input pin (only for P00 and P01)
 - Set the bit in the AIDRL register corresponding to the comparator input pin to "0".
 - Regardless of the value of the PDR0 register and that of the DDR0 register, if the comparator analog input enable bit in the comparator control register (CMR0C:VCID) is set to "0", the comparator input function is enabled.
 - To disable the comparator input function, set the VCID bit to "1".
 - For details of the comparator, refer to "CHAPTER 27 COMPARATOR" in "New 8FX MB95630H Series Hardware Manual".

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15.2 Port 1

Port 1 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.2.1 Port 1 configuration

Port 1 is made up of the following elements.

- · General-purpose I/O pins/peripheral function I/O pins
- Port 1 data register (PDR1)
- Port 1 direction register (DDR1)
- Port 1 pull-up register (PUL1)

15.2.2 Block diagrams of port 1

• P10/PPG10/CMP0 O pin

This pin has the following peripheral functions:

- 8/16-bit PPG ch. 1 output pin (PPG10)
- Comparator digital output pin (CMP0_O)
- P11/PPG11 pin

This pin has the following peripheral function:

- 8/16-bit PPG ch. 1 output pin (PPG11)
- P13/PPG00 pin

This pin has the following peripheral function:

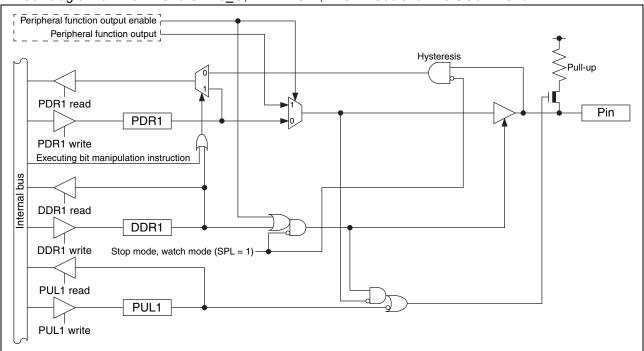
- 8/16-bit PPG ch. 0 output pin (PPG00)
- P15/UO0/PPG20 pin

This pin has the following peripheral functions:

- UART/SIO ch. 0 data output pin (UO0)
- 8/16-bit PPG ch. 2 output pin (PPG20)



• Block diagram of P10/PPG10/CMP0_O, P11/PPG11, P13/PPG00 and P15/UO0/PPG20



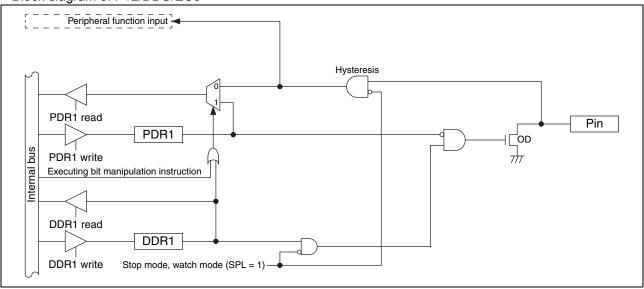


• P12/DBG/EC0 pin

This pin has the following peripheral functions:

- DBG input pin (DBG)
- 8/16-bit composite timer ch. 0 clock input pin (EC0)

Block diagram of P12/DBG/EC0



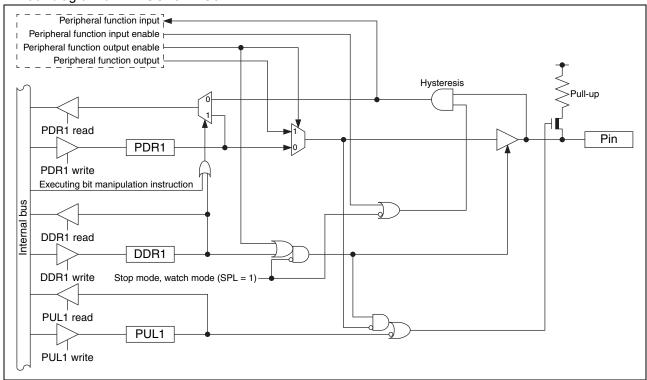
• P14/UCK0/PPG01 pin

This pin has the following peripheral functions:

- UART/SIO ch. 0 clock I/O pin (UCK0)
- 8/16-bit PPG ch. 0 output pin (PPG01)



• Block diagram of P14/UCK0/PPG01



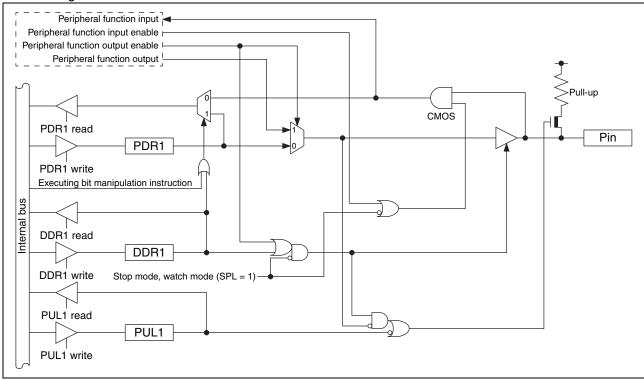


• P16/UI0/PPG21 pin

This pin has the following peripheral functions:

- UART/SIO ch. 0 data input pin (UI0)
- 8/16-bit PPG ch. 2 output pin (PPG21)

Block diagram of P16/UI0/PPG21



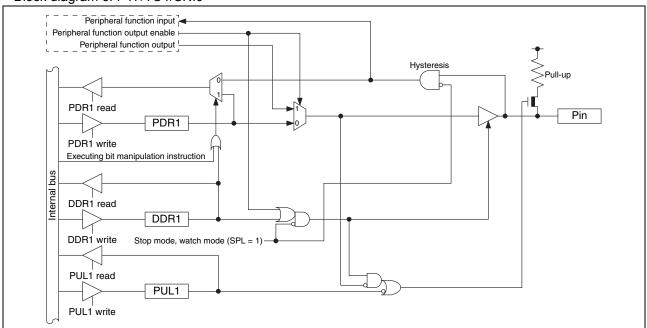
• P17/TO1/SNI0 pin

This pin has the following peripheral functions:

- 16-bit reload timer ch. 1 output pin (TO1)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI0)



• Block diagram of P17/TO1/SNI0





15.2.3 Port 1 registers

Port 1 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write			
PDR1	0	Pin state is "L" level.	PDR1 value is "0".	As output port, outputs "L" level.			
1		Pin state is "H" level.	PDR1 value is "1".	As output port, outputs "H" level.*			
DDR1	0		Port input enabled	d			
DDRI	1		Port output enabled				
PUL1	0		Pull-up disabled				
PULT	1		Pull-up enabled				

^{*:} If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

· Correspondence between registers and pins for port 1

	Correspondence between related register bits and pins										
Pin name	P17	P16	P15	P14	P13	P12	P11	P10			
PDR1											
DDR1	bit7	bit6	bit5	bit4	bit3	bit2*	bit1	bit0			
PUL1											

^{*:} Though P12 has no pull-up function, bit2 in the PUL1 register can still be accessed. The operation of P12 is not affected by the setting of bit2 in the PUL1 register.

15.2.4 Port 1 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR1 register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR1 register to external pins.
 - If data is written to the PDR1 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR1 register returns the PDR1 register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDR1 register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDR1 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR1 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR1 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR1 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR1 register corresponding to the input pin of a peripheral function

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to "0".

- Reading the PDR1 register returns the pin value, regardless of whether the peripheral function uses that pin as its
 input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1
 register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDR1 register are initialized to "0" and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR1 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input of P14/UCK0 and P16/UI0 is enabled by the external interrupt control register ch. 0 (EIC00) of the external interrupt circuit and the interrupt pin selection circuit control register (WICR) of the interrupt pin selection circuit, the input is enabled and is not blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register

Setting the bit in the PUL1 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL1 register.

15.3 Port 6

Port 6 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.3.1 Port 6 configuration

Port 6 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 6 data register (PDR6)
- Port 6 direction register (DDR6)
- Port 6 pull-up register (PUL6)

15.3.2 Block diagrams of port 6

P60/INT08/SDA/DTTI pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT08)
- I2C bus interface ch. 0 data I/O pin (SDA)
- MPG waveform sequencer input pin (DTTI)
- P61/INT09/SCL/TI1 pin

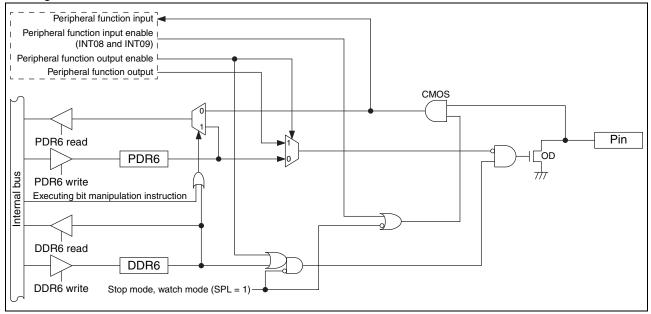
This pin has the following peripheral functions:

- External interrupt circuit input pin (INT09)
- I²C bus interface ch. 0 clock I/O pin (SCL)
- 16-bit reload timer ch. 1 input pin (TI1)

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Block diagram of P60/INT08/SDA/DTTI and P61/INT09/SCL/TI1



• P62/TO10/PPG00/OPT0 pin

This pin has the following peripheral functions:

- 8/16-bit composite timer ch. 1 output pin (TO10)
- 8/16-bit PPG ch. 0 output pin (PPG00)
- MPG waveform sequencer output pin (OPT0)

• P63/TO11/PPG01/OPT1 pin

This pin has the following peripheral functions:

- 8/16-bit composite timer ch. 1 output pin (TO11)
- 8/16-bit PPG ch. 0 output pin (PPG01)
- MPG waveform sequencer output pin (OPT1)

• P65/PPG11/OPT3 pin

This pin has the following peripheral functions:

- 8/16-bit PPG ch. 1 output pin (PPG11)
- MPG waveform sequencer output pin (OPT3)

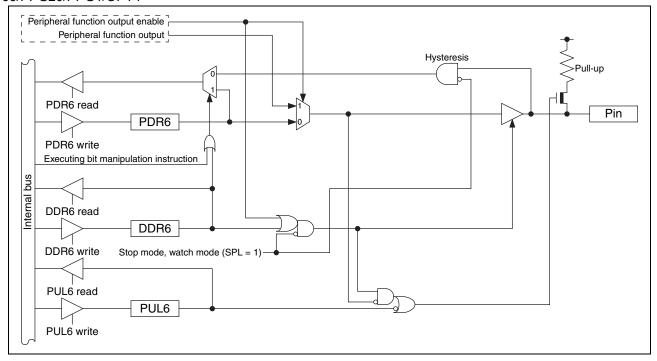
• P66/PPG20/PPG1/OPT4 pin

This pin has the following peripheral functions:

- 8/16-bit PPG ch. 2 output pin (PPG20)
- 16-bit PPG timer ch. 1 output pin (PPG1)
- MPG waveform sequencer output pin (OPT4)
- Block diagram of P62/TO10/PPG00/OPT0, P63/TO11/PPG01/OPT1, P65/PPG11/OPT3 and



P66/PPG20/PPG1/OPT4



• P64/EC1/PPG10/OPT2 pin

This pin has the following peripheral functions:

- 8/16-bit composite timer ch. 1 clock input pin (EC1)
- 8/16-bit PPG ch. 1 output pin (PPG10)
- MPG waveform sequencer output pin (OPT2)

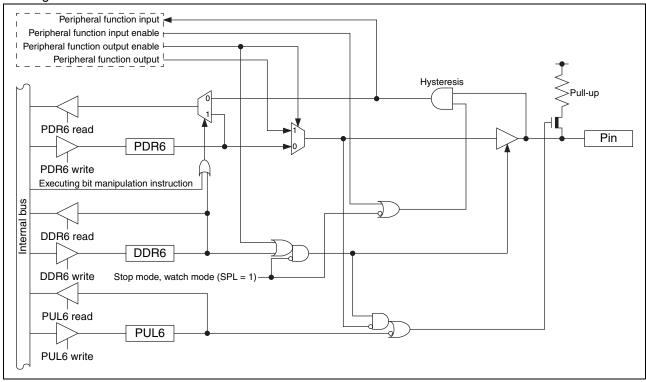
• P67/PPG21/TRG1/OPT5 pin

This pin has the following peripheral functions:

- 8/16-bit PPG ch. 2 output pin (PPG21)
- 16-bit PPG timer ch. 1 trigger input pin (TRG1)
- MPG waveform sequencer output pin (OPT5)



• Block diagram of P64/EC1/PPG10/OPT2 and P67/PPG21/TRG1/OPT5



15.3.3 Port 6 registers

· Port 6 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write			
PDR6	0	Pin state is "L" level.	PDR6 value is "0".	As output port, outputs "L" level.			
FDRO	1	Pin state is "H" level.	PDR6 value is "1".	As output port, outputs "H" level.*			
DDR6	0		Port input enabled				
DDRO	1		Port output enabled				
PUL6	0		Pull-up disabled				
FULO	1		Pull-up enabled				

^{*:} If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

• Correspondence between registers and pins for port 6

	Correspondence between related register bits and pins									
Pin name	P67	P66	P65	P64	P63	P62	P61	P60		
PDR6							bit1	bit0		
DDR6	bit7	bit6	bit5	bit4	bit3	bit2	DILI	bito		
PUL6							-	-		



15.3.4 Port 6 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR6 register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR6 register to external pins.
 - If data is written to the PDR6 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR6 register returns the PDR6 register value.
- · Operation as an input port
 - A pin becomes an input port if the bit in the DDR6 register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDR6 register, the value is stored in the output latch but is not output to the pin set as an
 input port.
 - Reading the PDR6 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is
 used to read the PDR6 register, the PDR6 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR6 register even if the peripheral function output is enabled. Therefore, the
 output value of a peripheral function can be read by the read operation on the PDR6 register. However, if the readmodify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR6 register corresponding to the input pin of a peripheral function to "0".
 - Reading the PDR6 register returns the pin value, regardless of whether the peripheral function uses that pin as its
 input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6
 register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDR6 register are initialized to "0" and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR6 register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open. However, if the interrupt input from the external interrupt (INT08, INT09) is enabled, or if the interrupt input of P64/EC1 and P67/TRG1 is enabled by the external interrupt control register ch. 0 (EIC00) of the external interrupt circuit and the interrupt pin selection circuit control register (WICR) of the interrupt pin selection circuit, the input is enabled and is not blocked.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register

Setting the bit in the PUL6 register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PUL6 register.

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15.4 Port F

Port F is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.4.1 Port F configuration

Port F is made up of the following elements.

- · General-purpose I/O pins/peripheral function I/O pins
- Port F data register (PDRF)
- Port F direction register (DDRF)

15.4.2 Block diagrams of port F

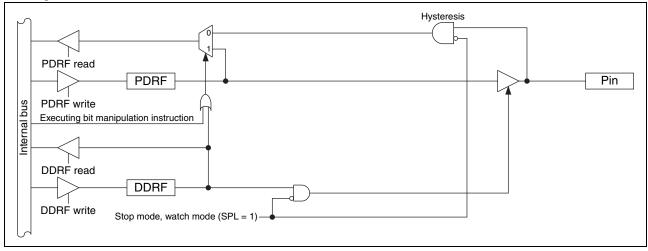
• PF0/X0 pin

This pin has the following peripheral function:

- Main clock input oscillation pin (X0)
- PF1/X1 pin

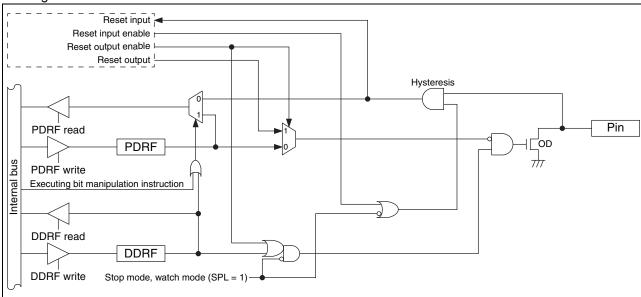
This pin has the following peripheral function:

- Main clock I/O oscillation pin (X1)
- · Block diagram of PF0/X0 and PF1/X1





- PF2/RST pin
 - This pin has the following peripheral function:
 - Reset pin (RST)
- Block diagram of PF2/RST



15.4.3 Port F registers

Port F register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write			
PDRF	0	Pin state is "L" level.	PDRF value is "0".	As output port, outputs "L" level.			
FDIXI	1	Pin state is "H" level.	PDRF value is "1".	As output port, outputs "H" level.*			
DDRF	0		Port input enabled				
DDIN	1		Port output enable	d			

^{*:} If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

Correspondence between registers and pins for port F

	Correspondence between related register bits and pins									
Pin name	-	-	-	-	-	PF2*	PF1	PF0		
PDRF						bit2	bit1	bit0		
DDRF	-	-	-	-	-	DILZ	DILI	DILO		

^{*:} PF2/RST is the dedicated reset pin on MB95F632H/F633H/F634H/F636H.

15.4.4 Port F operations

- · Operation as an output port
 - A pin becomes an output port if the bit in the DDRF register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDRF register to external pins.
 - If data is written to the PDRF register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDRF register returns the PDRF register value.



- · Operation as an input port
 - A pin becomes an input port if the bit in the DDRF register corresponding to that pin is set to "0".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDRF register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDRF register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRF register, the PDRF register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDRF register are initialized to "0" and port input is enabled.

- · Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRF register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open.
 - If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

15.5 Port G

Port G is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in "New 8FX MB95630H Series Hardware Manual".

15.5.1 Port G configuration

Port G is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port G data register (PDRG)
- Port G direction register (DDRG)
- Port G pull-up register (PULG)

15.5.2 Block diagram of port G

PG1/X0A/SNI1 pin

This pin has the following peripheral functions:

- Subclock input oscillation pin (X0A)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI1)
- PG2/X1A/SNI2 pin

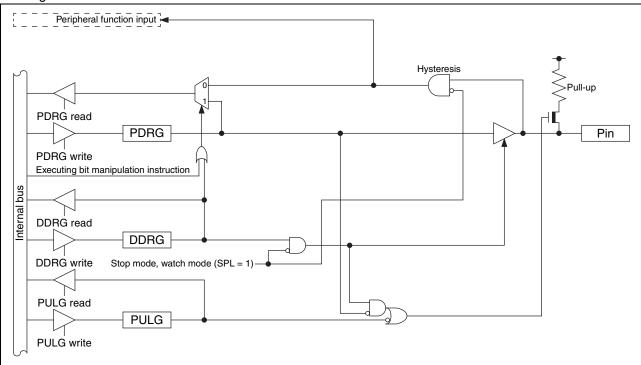
This pin has the following peripheral functions:

- Subclock I/O oscillation pin (X1A)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI2)

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Block diagram of PG1/X0A/SNI1 and PG2/X1A/SNI2



15.5.3 Port G registers

· Port G register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write				
PDRG 0		Pin state is "L" level.	PDRG value is "0".	As output port, outputs "L" level.				
FDRG	1	Pin state is "H" level.	PDRG value is "1".	As output port, outputs "H" level.				
DDRG	0		Port input enabled					
DDRG	1		Port output enabled					
PULG	0	Pull-up disabled						
FOLG	1		Pull-up enabled					

· Correspondence between registers and pins for port G

		Correspondence between related register bits and pins									
Pin name	-	-	-	-	-	PG2	PG1	-			
PDRG											
DDRG	-	-	-	-	-	bit2	bit1	-			
PULG											

15.5.4 Port G operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDRG register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDRG register to external pins.



- If data is written to the PDRG register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDRG register returns the PDRG register value.

Operation as an input port

- · A pin becomes an input port if the bit in the DDRG register corresponding to that pin is set to "0".
- For a pin shared with other peripheral functions, disable the output of such peripheral functions.
- If data is written to the PDRG register, the value is stored in the output latch but is not output to the pin set as an input port.
- Reading the PDRG register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.

Operation as a peripheral function input pin

- To set a pin as an input port, set the bit in the DDRG register corresponding to the input pin of a peripheral function to "0".
- Reading the PDRG register returns the pin value, regardless of whether the peripheral function uses that pin as its
 input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG
 register value is returned.

Operation at reset

If the CPU is reset, all bits in the DDRG register are initialized to "0" and port input is enabled.

· Operation in stop mode and watch mode

- If the pin state setting bit in the standby control register (STBC:SPL) is set to "1" and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRG register value. The input of that pin is locked to "L" level and blocked in order to prevent leaks due to input open.
- If the pin state setting bit is "0", the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

Operation of the pull-up register

Setting the bit in the PULG register to "1" makes the pull-up resistor be internally connected to the pin. When the pin output is "L" level, the pull-up resistor is disconnected regardless of the value of the PULG register.

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16. Interrupt Source Table

	Interrupt		r table ress		pt level register	Priority order of interrupt sources
Interrupt source	request number	Upper	Lower	Register	Bit	of the same level (occurring simultaneously)
External interrupt ch. 0	IRQ00	0xFFFA	0xFFFB	ILR0	L00 [1:0]	High
External interrupt ch. 4	111000	OXITIA	OXITID	ILIXO	L00 [1.0]	A
External interrupt ch. 1	IRQ01	0xFFF8	0xFFF9	ILR0	L01 [1:0]	T
External interrupt ch. 5	11/0/01	UXITIO	OXIII3	ILINO	LOT [1.0]	
External interrupt ch. 2	IRQ02	0xFFF6	0xFFF7	ILR0	L02 [1:0]	
External interrupt ch. 6	11/0/02	UXITIU	OXI I I I	ILINO	L02 [1.0]	
External interrupt ch. 3	IRQ03	0xFFF4	0xFFF5	ILR0	L03 [1:0]	
External interrupt ch. 7	11/000	UXI I I T	UXITIO	ILINO	L03 [1.0]	
UART/SIO ch. 0	IRQ04	0xFFF2	0xFFF3	ILR1	L04 [1:0]	
MPG (DTTI)	11/004	UNITIZ	UXITIO	ILIXI	L04 [1.0]	
8/16-bit composite timer ch. 0	IRQ05	0xFFF0	0xFFF1	ILR1	L05 [1:0]	
(lower)	IIXQUU	UXITIU	UXIIII	ILIXI	L03 [1.0]	
8/16-bit composite timer ch. 0	IRQ06	0xFFEE	0xFFEF	ILR1	L06 [1:0]	
(upper)	IRQUU	UXFFEE	UXFFEF	ILKI	L00 [1.0]	
LIN-UART (reception)	IRQ07	0xFFEC	0xFFED	ILR1	L07 [1:0]	
LIN-UART (transmission)	IRQ08	0xFFEA	0xFFEB	ILR2	L08 [1:0]	
8/16-bit PPG ch. 1 (lower)	IRQ09	0xFFE8	0xFFE9	ILR2	L09 [1:0]	
8/16-bit PPG ch. 1 (upper)	IRQ10	0xFFE6	0xFFE7	ILR2	L10 [1:0]	
8/16-bit PPG ch. 2 (upper)	IRQ11	0xFFE4	0xFFE5	ILR2	L11 [1:0]	
8/16-bit PPG ch. 0 (upper)	IRQ12	0xFFE2	0xFFE3	ILR3	L12 [1:0]	
8/16-bit PPG ch. 0 (lower)	IRQ13	0xFFE0	0xFFE1	ILR3	L13 [1:0]	
8/16-bit composite timer ch. 1	IRQ14	0xFFDE	0xFFDF	ILR3	1 4 4 [4:0]	
(upper)	IKQ 14	UXFFDE	UXFFDF	ILKS	L14 [1:0]	
8/16-bit PPG ch. 2 (lower)	IRQ15	0xFFDC	0xFFDD	ILR3	L15 [1:0]	
16-bit reload timer ch. 1						
MPG (write timing/compare clear)	IRQ16	0xFFDA	0xFFDB	ILR4	L16 [1:0]	
I ² C bus interface						
16-bit PPG timer ch. 1						
MPG (position detection/compare	IRQ17	0xFFD8	0xFFD9	ILR4	L17 [1:0]	
interrupt)						
8/10-bit A/D converter	IRQ18	0xFFD6	0xFFD7	ILR4	L18 [1:0]	
Time-base timer	IRQ19	0xFFD4	0xFFD5	ILR4	L19 [1:0]	
Watch prescaler			0vEED2			
Comparator	IRQ20	0xFFD2	0xFFD3	ILR5	L20 [1:0]	
External interrupt ch. 8	IDC04	٥٧٢٢٥٥	0	II D.c	1.04 [4.0]	
External interrupt ch. 9	IRQ21	0xFFD0	0xFFD1	ILR5	L21 [1:0]	
8/16-bit composite timer ch. 1	IDCCC	٥٧٢٢٥٢	٥٧٢٢٥٢	II D.c	1.00 [4.0]	
(lower)	IRQ22	0xFFCE	0xFFCF	ILR5	L22 [1:0]	
Flash memory	IRQ23	0xFFCC	0xFFCD	ILR5	L23 [1:0]	▼ Low



17. Pin States In Each Mode

	Normal		Stop	mode	Watch	mode	
Pin name	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	On reset
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	_
PF0/X0	I/O port*4	I/O port*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	_
PF1/X1	I/O port*4	I/O port*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	_
PG1/X0A/ SNI1	I/O port*4/ peripheral func- tion I/O	I/O port*4/ peripheral func- tion I/O	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	_
SNI2	I/O port*4/ peripheral function I/O	I/O port*4/ peripheral function I/O	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Hi-Z - Input enabled* ¹ (However, it does not function.)
PF2/RST	I/O port	Reset input	Reset input	Reset input	Reset input	Reset input	Reset input*3
P61/INT09/	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	 Previous state kept Input blocked*² (However, an external interrupt can be input when the external 	- Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external	 Previous state kept Input blocked*² (However, an external interrupt can be input when the external 	- Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external	- Hi-Z - Input enabled*1 (However, it does not
SCL/TI1			interrupt request is enabled.)	interrupt request is enabled.)	interrupt request is enabled.)	interrupt request is enabled.)	function.)
01 10	I/O port/ peripheral	I/O port/ peripheral	- Previous state kept	- Hi-Z (However, the setting of the pull-up	- Previous state kept	- Hi-Z (However, the setting of the pull-up	- Hi-Z - Input enabled*1
P63/TO11/ PPG01/ OPT1	function I/O	function I/O	- Input blocked*2	control is effective.) - Input blocked*2	- Input blocked*2	control is effective.) - Input blocked*2	(However, it does not function.)

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Dia nama	Normal	Class made	Stop	mode	Watch	mode	0
Pin name	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	On reset
P64/EC1/ PPG10/ OPT2	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z - Input enabled* ¹ (However, it does not function.)
P65/PPG11/ OPT3 P66/PPG1/ PPG20/ OPT4	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*² 	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	- Hi-Z - Input enabled*1 (However, it does not function.)
P67/TRG1/ PPG21/ OPT5	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z - Input enabled* ¹ (However, it does not function.)
P10/PPG10/ CMP0_O	I/O port/ peripheral	I/O port/ peripheral	- Previous state kept	- Hi-Z (However, the setting of the pull-up control is	- Previous state kept	- Hi-Z (However, the setting of the pull-up control is	- Hi-Z - Input enabled*1 (However, it
P11/PPG11	function I/O	function I/O	- Input blocked*2	effective.) - Input blocked*2	- Input blocked*2	effective.) - Input blocked*2	does not function.)
P12/DBG/ EC0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	- Hi-Z - Input blocked*2	- Previous state kept - Input blocked*2	- Hi-Z - Input blocked* ²	- Hi-Z - Input enabled* ¹ (However, it does not function.)
P13/PPG00	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	- Hi-Z - Input enabled* ¹ (However, it does not function.)



Din nama	Normal	Class made	Stop	mode	Watch	mode	0======		
Pin name	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	On reset		
P14/UCK0/ PPG01	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	- Hi-Z - Input enabled* ¹ (However, it does not function.)		
P15/UO0/ PPG20	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*² 	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	- Hi-Z - Input enabled*1 (However, it does not function.)		
P16/UI0/ PPG21	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) 	- Hi-Z - Input enabled*1 (However, it does not function.)		
P17/TO1/ SNI0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*² 	- Previous state kept - Input blocked*2	 Hi-Z (However, the setting of the pull-up control is effective.) Input blocked*2 	- Hi-Z - Input enabled* ¹ (However, it does not function.)		
P00/INT00/ AN00/ CMP0_P			- Previous state kept	- Hi-Z (However, the setting of the pull-up	- Previous state kept	- Hi-Z (However, the setting of the pull-up			
CIVIEU IN	I/O port/ peripheral	I/O port/ peripheral	- Input blocked*2 (However, an external	control is effective.) - Input blocked*2 (However, an	 Input blocked*2 (However, an external 	control is effective.) - Input blocked*2 (However, an	- Hi-Z		
P02/INT02/ AN02/SCK	function I/O/ analog input	on I/O/ function I/O/	interrupt can be input when the external	external interrupt can be input when	interrupt can be input when the external	external interrupt can be input when	- Input blocked*2		
P03/INT03/ AN03/SOT	red		interrupt request is enabled.)	the external interrupt request is enabled.)	interrupt request is enabled.)	the external interrupt request is enabled.)			



Pin name	Normal	Sleep mode	Stop	mode	Watch	mode	On reset
Pili lialile	operation	Sleep mode	SPL=0	SPL=1	SPL=0	SPL=1	Onreset
P04/INT04/ AN04/SIN/ EC0			- Previous state kept	 Hi-Z (However, the setting of the pull-up 	- Previous state kept	 Hi-Z (However, the setting of the pull-up 	
P05/INT05/ AN05/TO00	I/O port/	I/O port/	- Input blocked*2 (However, an	control is effective.) - Input blocked*2	- Input blocked*2 (However, an	control is effective.) - Input blocked*2	
P06/INT06/ AN06/TO01	peripheral function I/O/	peripheral function I/O/	external interrupt can	(However, an external	external interrupt can	(However, an external	- Hi-Z - Input blocked* ²
P07/INT07/ AN07	analog input	analog input	be input when the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	be input when the external interrupt request is enabled.)	interrupt can be input when the external interrupt request is enabled.)	DIOCKEU -

SPL: Pin state setting bit in the standby control register (STBC:SPL)

Hi-Z: High impedance

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^{*1: &}quot;Input enabled" means that the input function is enabled. While the input function is enabled, a pull-up or pull-down operation has to be performed in order to prevent leaks due to external input. If a pin is used as an output port, its pin state is the same as that of other ports.

^{*2: &}quot;Input blocked" means direct input gate operation from the pin is disabled.

^{*3:} The PF2/RST pin stays at the state shown when configured as a reset pin.

^{*4:} The pin stays at the state shown when configured as a general-purpose I/O port.



18. Electrical Characteristics

18.1 Absolute Maximum Ratings

Danamatan	Ob. a.l.	Rat	ing	11	Domonto
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage*1	Vcc	Vss - 0.3	Vss + 6	V	
Input voltage*1	Vı	Vss - 0.3	Vss + 6	V	*2
Output voltage*1	Vo	Vss - 0.3	Vss + 6	V	*2
Maximum clamp current	ICLAMP	-2	+2	mA	Applicable to specific pins*3
Total maximum clamp current	Σ CLAMP	_	20	mA	Applicable to specific pins*3
"L" level maximum output current	Ю	_	15	mA	
"L" level average current	lolav1		4	- mA	Other than P62 to P67 Average output current = operating current × operating ratio (1 pin)
L level average current	lolav2		12	IIIA	P62 to P67 Average output current = operating current × operating ratio (1 pin)
"L" level total maximum output current	Σ lol	_	100	mA	
"L" level total average output current	Σ Iolav	_	37	mA	Total average output current = operating current × operating ratio (Total number of pins)
"H" level maximum output current	Іон	_	-15	mA	
"H" level average	Iонаv1		-4	mA	Other than P62 to P67 Average output current = operating current × operating ratio (1 pin)
current	Iонаv2		-8	IIIA	P62 to P67 Average output current = operating current × operating ratio (1 pin)
"H" level total maximum output current	Σ Іон	_	-100	mA	
"H" level total average output current	Σ Iohav	_	-47	mA	Total average output current = operating current × operating ratio (Total number of pins)
Power consumption	Pd	_	320	mW	
Operating temperature	Та	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

^{*1:} These parameters are based on the condition that Vss is 0.0 V.

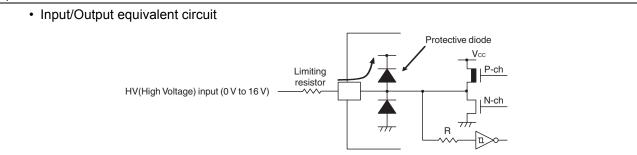
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^{*2:} V₁ and V₀ must not exceed V_{CC} + 0.3 V. V₁ must not exceed the rated voltage. However, if the maximum current to/from an input is limited by means of an external component, the I_{CLAMP} rating is used instead of the V₁ rating.

^{*3:} Specific pins: P00 to P07, P10, P11, P13 to P17, P62 to P67, PF0, PF1, PG1, PG2



- · Use under recommended operating conditions.
- · Use with DC voltage (current).
- The HV (High Voltage) signal is an input signal exceeding the Vcc voltage. Always connect a limiting resistor between the HV (High Voltage) signal and the microcontroller before applying the HV (High Voltage) signal.
- The value of the limiting resistor should be set to a value at which the current to be input to the microcontroller pin when the HV (High Voltage) signal is input is below the standard value, irrespective of whether the current is transient current or stationary current.
- When the microcontroller drive current is low, such as in low power consumption modes, the HV (High Voltage) input potential may pass through the protective diode to increase the potential of the Vcc pin, affecting other devices.
- If the HV (High Voltage) signal is input when the microcontroller power supply is off (not fixed at 0 V), since power is supplied from the pins, incomplete operations may be executed.
- If the HV (High Voltage) input is input after power-on, since power is supplied from the pins, the voltage of power supply may not be sufficient to enable a power-on reset.
- Do not leave the HV (High Voltage) input pin unconnected.
- · Example of a recommended circuit:



WARNING: Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings.

Do not exceed any of these ratings.

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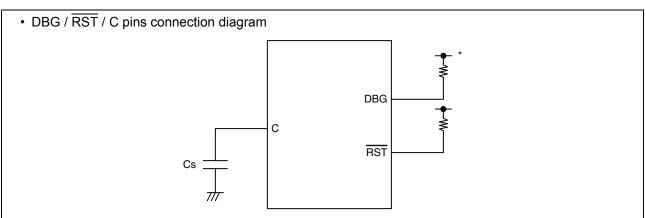


18.2 Recommended Operating Conditions

(Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks		
Parameter	Syllibol	Min	Max	Ullit	iveillat ka		
Power supply voltage	Vcc	2.4*1	5.5	V	In normal operation		
Fower supply voltage	VCC	2.3	5.5	V	Hold condition in stop mode		
Decoupling capacitor	Cs	Cs 0.022		μF	*2		
Operating temperature	TA	- 40	+85	°C	Other than on-chip debug mode		
Operating temperature	IA	+5	+35		On-chip debug mode		

- *1: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used or when the on-chip debug mode is used.
- *2: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs. For the connection to a decoupling capacitor Cs, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and Cs and the distance between Cs and the Vss pin when designing the layout of a printed circuit board.



*: Connect the DBG pin to an external pull-up resistor of $2 \text{ k}\Omega$ or above. After power-on, ensure that the DBG pin does not stay at "L" level until the reset output is released. The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition.

Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.



18.3 DC Characteristics

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, TA = -40 °C to +85°C)

					Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
	Vihi	P04, P16, P60, P61	_	0.7 Vcc	_	Vcc + 0.3	V	CMOS input level
"H" level input voltage	Vihs	P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2	_	0.8 Vcc	_	Vcc + 0.3	>	Hysteresis input
	Vінм	PF2	_	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input
	VILI	P04, P16, P60, P61	_	Vss - 0.3	_	0.3 Vcc	>	CMOS input level
"L" level input voltage	VILS	P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2	_	Vss – 0.3	_	0.2 Vcc	V	Hysteresis input
	VILM	PF2	_	Vss - 0.3	_	0.2 Vcc	V	Hysteresis input
Open-drain output application voltage	VD	P12, P60, P61, PF2	_	Vss - 0.3	_	Vss + 5.5	٧	
"H" level output voltage	Vон1	Output pins other than P12, P62 to P67, PF2	Iон = -4 mA	Vcc – 0.5	_	_	٧	
	V _{OH2}	P62 to P67	Iон = -8 mA	Vcc - 0.5	_	_	V	
"L" level output voltage	V _{OL1}	Output pins other than P62 to P67	IoL = 4 mA	_	_	0.4	V	
voitage	V _{OL2}	P62 to P67	IoL = 12 mA	_		0.4	V	
Input leak current (Hi-Z output leak current)	lu	All input pins	0.0 V < Vı < Vcc	-5	_	+5	μA	When the internal pull-up resistor is disabled
Internal pull-up resistor	Rpull	P00 to P07, P10, P11, P13 to P17, P62 to P67, PG1, PG2	V _I = 0 V	25	50	100	kΩ	When the internal pull-up resistor is enabled
Input capacitance	Cin	Other than Vcc and Vss	f = 1 MHz	_	5	15	pF	



 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, TA = -40 °C to +85°C)$

					Value	,		V, TA = 40 0 to 100 0
Parameter	Symbol	Pin name	Condition	Min	Typ*1	Max*2	Unit	Remarks
			FcH = 32 MHz		3.6	5.8	mA	Except during Flash memory programming and erasing
	Icc		FMP = 16 MHz Main clock mode (divided by 2)		7.5	13.8	mA	During Flash memory programming and erasing
				_	4.1	9.1	mΑ	At A/D conversion
	Iccs		F _{CH} = 32 MHz F _{MP} = 16 MHz Main sleep mode (divided by 2)		1.3	3	mA	
	Iccl	Vcc (External clock operation)	Fcl = 32 kHz FMPL = 16 kHz Subclock mode (divided by 2) TA = +25°C		49	145	μΑ	
Power	Iccls		F _{CL} = 32 kHz F _{MPL} = 16 kHz Subsleep mode (divided by 2) T _A = +25°C		10	15	μΑ	In deep standby mode
supply current*3	Ісст		F _{CL} = 32 kHz Watch mode Main stop mode T _A = +25°C	_	7	13	μA	In deep standby mode
	ICCMPLL		FMCRPLL = 16 MHz FMP = 16 MHz Main CR PLL clock mode (multiplied by 4) TA = +25°C	_	4.7	6.8	mA	
	Іссмск	Vcc	F _{CRH} = 4 MHz F _{MP} = 4 MHz Main CR clock mode	_	1.1	4.6	mA	
	Iccscr		Sub-CR clock mode (divided by 2) T _A = +25°C	_	58.1	230	μΑ	
	Ісстѕ	Vcc (External clock	F _{CH} = 32 MHz Time-base timer mode T _A = +25°C	_	345	395	μΑ	In deep standby mode
	Іссн	operation)	Substop mode T _A = +25°C	_	6	10	μA	In deep standby mode



 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ TA} = -40 \,^{\circ}\text{C to} + 85\,^{\circ}\text{C})$

Damamatan	Ola a l	Din mana	O a maliti a m		Value		11:4	Demonto
Parameter	Symbol	Pin name	Condition	Min	Typ*1	Max*2	Unit	Remarks
	lv		Current consumption of the comparator	_	60	160	μΑ	
	ILVD		Current consumption of the low-voltage detection circuit	_	4	7	μΑ	
Power	Icrh		Current consumption of the main CR oscillator	—	240	320	μΑ	
supply current*3	ICRL	Vcc	Current consumption of the sub-CR oscillator oscillating at 100 kHz	_	7	20	μΑ	
	Імѕтву		Current consumption difference between normal standby mode and deep standby mode TA = +25°C	_	20	30	μΑ	

^{*1:} $V_{CC} = 5.0 \text{ V}$, $T_A = +25^{\circ}\text{C}$

- See "4. AC Characteristics Clock Timing" for Fch, Fcl, Fcrh and Fmcrpll.
- See "4. AC Characteristics Source Clock/Machine Clock" for FMP and FMPL.
- The power supply current value in standby mode is measured in deep standby mode. The current consumption in normal standby is higher than that in deep standby mode. The power supply current value in normal standby can be found by adding the current consumption difference between normal standby mode and deep standby mode (Instby) to the power supply current value in deep standby mode. For details of normal standby and deep standby mode, refer to "CHAPTER 3 CLOCK CONTROLLER" in "New 8FX MB95630H Series Hardware Manual".

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^{*2:} Vcc = 5.5 V, $T_A = +85^{\circ}\text{C}$ (unless otherwise specified)

^{*3: •} The power supply current is determined by the external clock. When the low-voltage detection circuit is selected, the power supply current is the sum of adding the current consumption of the low-voltage detection circuit (ILVD) to one of the values from Icc to Icch. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current is the sum of adding up the current consumption of the low-voltage detection circuit (ILVD), the current consumption of the CR oscillators (ICRH, ICRL) and a specified value. In on-chip debug mode, the CR oscillator (ICRH) and the low-voltage detection circuit are always in operation, and current consumption therefore increases accordingly.



18.4 AC Characteristics

18.4.1 Clock Timing

(Vcc = 2.4 V to 5.5 V, Vss = 0.0 V, $T_A = -40^{\circ}C$ to $+85^{\circ}C$)

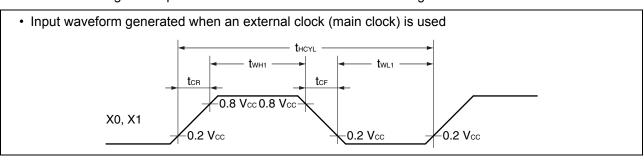
			_		Value			, vss - 0.0 v, 1A40 C to +0
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
	Fсн	X0, X1	_	1	_	16.25	MHz	When the main oscillation circuit is used
	ГСН	X0	X1: open	1	_	12	MHz	When the main external clock
		X0, X1	*	1	_	32.5	MHz	is used
				3.92	4	4.08	MHz	Operating conditions • The main CR clock is used. • $0^{\circ}C \le T_A \le +70^{\circ}C$
	Fcrh	_	_	3.8	4	4.2	MHz	 Operating conditions The main CR clock is used. - 40 °C ≤ TA < 0 °C, + 70 °C < TA ≤ + 85 °C
				7.84	8	8.16	MHz	Operating conditions • PLL multiplication rate: 2 • $0^{\circ}C \le T_A \le +70^{\circ}C$
				7.6	8	8.4	MHz	Operating conditions • PLL multiplication rate: 2 • − 40 °C ≤ TA < 0 °C, + 70 °C < TA ≤ + 85 °C
				9.8	10	10.2	MHz	Operating conditions • PLL multiplication rate: 2.5 • $0^{\circ}C \le T_A \le +70^{\circ}C$
Clock frequency	_			9.5	10	10.5	MHz	 Operating conditions PLL multiplication rate: 2.5 - 40 °C ≤ TA < 0 °C, + 70 °C < TA ≤ + 85 °C
	FMCRPLL	_	_	11.76	12	12.24	MHz	Operating conditions • PLL multiplication rate: 3 • $0^{\circ}C \le T_A \le +70^{\circ}C$
				11.4	12	12.6	MHz	Operating conditions • PLL multiplication rate: 3 • − 40 °C ≤ TA < 0 °C, + 70 °C < TA ≤ + 85 °C
				15.68	16	16.32	MHz	Operating conditions • PLL multiplication rate: 4 • $0^{\circ}C \le T_A \le +70^{\circ}C$
				15.2	16	16.8	MHz	Operating conditions • PLL multiplication rate: 4 • − 40 °C ≤ TA < 0 °C, + 70 °C < TA ≤ + 85 °C
	FcL	X0A, X1A		_	32.768	_	kHz	When the suboscillation circuit is used
	I CL	ΛυΑ, ΛΙΑ	_	_	32.768	_	kHz	When the sub-external clock is used
	Fcrl	_		50	100	150	kHz	When the sub-CR clock is used

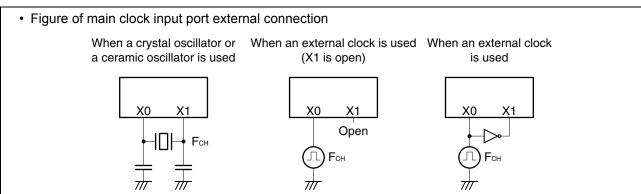


 $(Vcc = 2.4 \text{ V to } 5.5 \text{ V}, Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

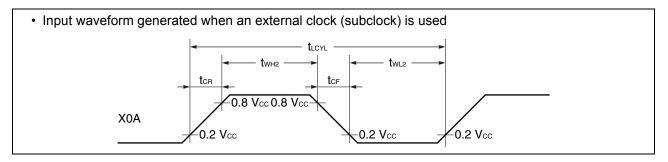
					Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
		X0, X1		61.5		1000	ns	When the main oscillation circuit is used
Clock cycle	t HCYL	X0	X1: open	83.4		1000	ns	When an external clock is
time		X0, X1	*	30.8	_	1000	ns	used
	tLCYL	X0A, X1A			30.5		μs	When the subclock is used
	5 5	X0	X1: open	33.4	_		ns	When an external clock is
Input clock pulse width	twh1, twl1	X0, X1	*	12.4	_			used, the duty ratio should
paice watii	twh2, twl2	X0A		_	15.2		μs	range between 40% and 60%.
Input clock		X0, X0A	X1: open	_		5	ns	When an external clock is
rising time and falling time	tcr, tcf	X0, X1, X0A, X1A	*	_	_	5	ns	used
CR oscillation	tcrhwk	_	_		_	50	μs	When the main CR clock is used
start time	t crlwk	_	_	_	_	30	μs	When the sub-CR clock is used
PLL oscillation start time	t MCRPLLWK	_	_	_		100	μs	When the main CR PLL clock is used

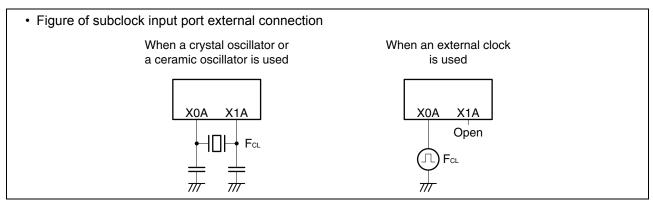
*: The external clock signal is input to X0 and the inverted external clock signal to X1.

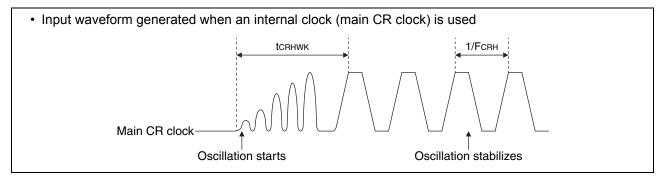


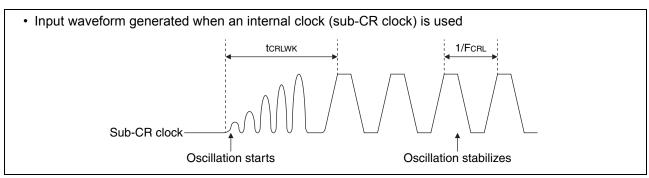




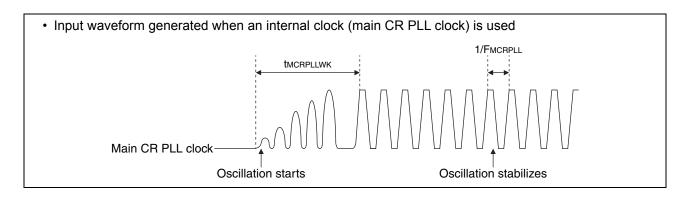












18.4.2 Source Clock/Machine Clock

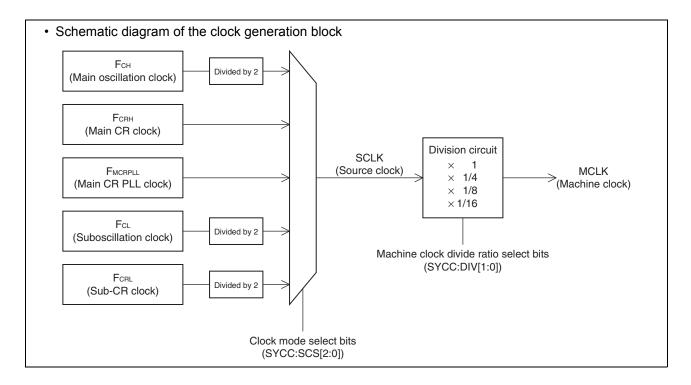
(Vcc = $5.0 \text{ V} \pm 10\%$, Vss = 0.0 V, TA = $-40 ^{\circ}\text{C}$ to $+85 ^{\circ}\text{C}$)

Doromotor	Symbol	Pin		Value		Unit	Remarks
Parameter	Symbol	name	Min	Тур	Max	Unit	Remarks
			61.5		2000	ns	When the main external clock is used Min: FcH = 32.5 MHz, divided by 2 Max: FcH = 1 MHz, divided by 2
Source clock cycle time*1	t sclk	_	62.5		250	ns	When the main CR clock is used Min: Fcrh = 4 MHz, multiplied by 4 Max: Fcrh = 4 MHz, no division
			_	61	_	μs	When the suboscillation clock is used FcL = 32.768 kHz, divided by 2
			_	20	_	μs	When the sub-CR clock is used FcL = 100 kHz, divided by 2
	Fsp		0.5	_	16.25	MHz	When the main oscillation clock is used
Source clock	FSP		_	4	_	MHz	When the main CR clock is used
frequency		_	_	16.384		kHz	When the suboscillation clock is used
	Fspl		_	50	_	kHz	When the sub-CR clock is used FCRL = 100 kHz, divided by 2
			61.5	_	32000	ns	When the main oscillation clock is used Min: F _{SP} = 16.25 MHz, no division Max: F _{SP} = 0.5 MHz, divided by 16
Machine clock cycle time*2 (minimum	t MCLK		250		4000	ns	When the main CR clock is used Min: F _{SP} = 4 MHz, no division Max: F _{SP} = 4 MHz, divided by 16
instruction execution time)	IMCLK	_	61	_	976.5	μs	When the suboscillation clock is used Min: F _{SPL} = 16.384 kHz, no division Max: F _{SPL} = 16.384 kHz, divided by 16
			20	_	320	μs	When the sub-CR clock is used Min: Fspl = 50 kHz, no division Max: Fspl = 50 kHz, divided by 16

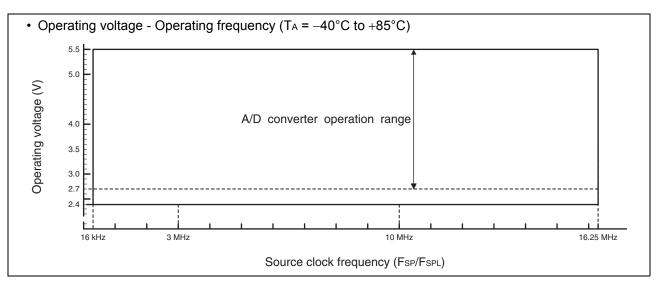


Parameter	Symbol	Symbol Pin Value		Unit	Remarks		
Parameter	Syllibol	name	Min	Тур	Max	5	Remarks
	Емр		0.031	_	16.25	MHz	When the main oscillation clock is used
Machine clock	IMP		0.25	_	16	MHz	When the main CR clock is used
frequency		_	1.024		16.384	kHz	When the suboscillation clock is used
, ,	FMPL		3.125		50	kHz	When the sub-CR clock is used FCRL = 100 kHz

- *1: This is the clock before it is divided according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). This source clock is divided to become a machine clock according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). In addition, a source clock can be selected from the following.
 - · Main clock divided by 2
 - · Main CR clock
 - PLL multiplication of main CR clock (Select a multiplication rate from 2, 2.5, 3 and 4.)
 - Subclock divided by 2
 - Sub-CR clock divided by 2
- *2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.
 - Source clock (no division)
 - · Source clock divided by 4
 - · Source clock divided by 8
 - · Source clock divided by 16





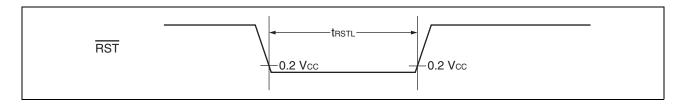


18.4.3 External Reset

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ TA} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

Parameter	Symbol	Value		Unit	Remarks
		Min	Max	Oilit	Remarks
RST "L" level pulse width	trstl	2 t MCLK*		ns	

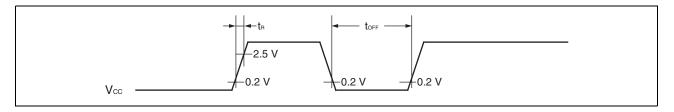
^{*:} See "Source Clock/Machine Clock" for tmclk.



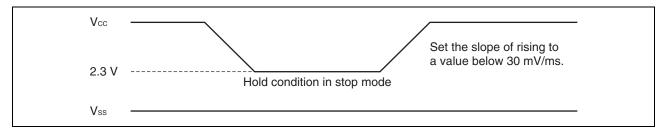


18.4.4 Power-on Reset

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Faranietei	Syllibol	Condition	Min	Max	Oilit	Remarks	
Power supply rising time	tr			50	ms		
Power supply cutoff time	t off		1		ms	Wait time until power-on	



Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.

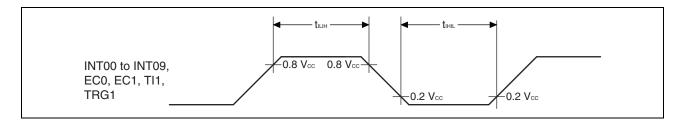


18.4.5 Peripheral Input Timing

 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, Ta = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol Pin name		Value		Unit
Faranietei	Syllibol	Finitianie	Min	Max	Oilit
Peripheral input "H" pulse width	tılıH	INT00 to INT09, EC0, EC1, TI1,	2 t мськ*		ns
Peripheral input "L" pulse width	tıнı∟	TRG1	2 t мськ*		ns

^{*:} See "Source Clock/Machine Clock" for tmclk.



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18.4.6 LIN-UART Timing

Sampling is executed at the rising edge of the sampling clock*1, and serial clock delay is disabled*2. (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

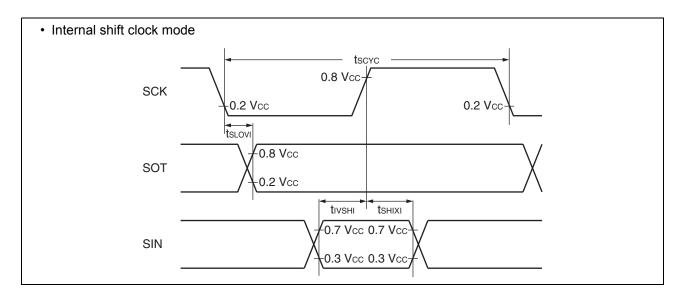
 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Symbol Pin name Condition		Va	lue	Unit
Parameter	Syllibol	Fill Hallie	Condition	Min	Max	Oilit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
$SCK \downarrow \rightarrow SOT$ delay time	t slovi	SCK, SOT	Internal clock operation output pin:	-50	+50	ns
Valid SIN → SCK↑	tıvsнı	SCK, SIN	C _L = 80 pF + 1 TTL	tmcLK*3 + 80	_	ns
$SCK \uparrow \rightarrow valid SIN hold time$	t shixi	SCK, SIN		0	_	ns
Serial clock "L" pulse width	t slsh	SCK		3 tмськ*3—tr	_	ns
Serial clock "H" pulse width	t shsl	SCK		tmcLK*3 + 10	_	ns
$SCK{\downarrow} o SOT$ delay time	t slove	SCK, SOT	External clock	_	2 tмськ* ³ + 60	ns
Valid SIN → SCK↑	tivshe	SCK, SIN	operation output pin:	30	_	ns
$SCK^{\uparrow} \rightarrow valid SIN hold time$	t shixe	SCK, SIN	C∟ = 80 pF + 1 TTL	tmcLK*3 + 30	_	ns
SCK falling time	tғ	SCK		_	10	ns
SCK rising time	t R	SCK			10	ns

^{*1:} There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

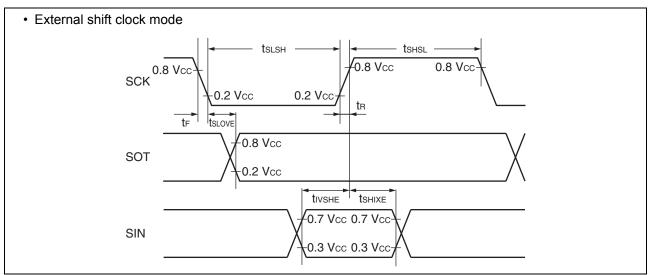
*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock/Machine Clock" for tmclk.



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Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is disabled*2. (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

(Vcc = $5.0 \text{ V} \pm 10\%$, Vss = 0.0 V, Ta = $-40 ^{\circ}\text{C}$ to $+85 ^{\circ}\text{C}$)

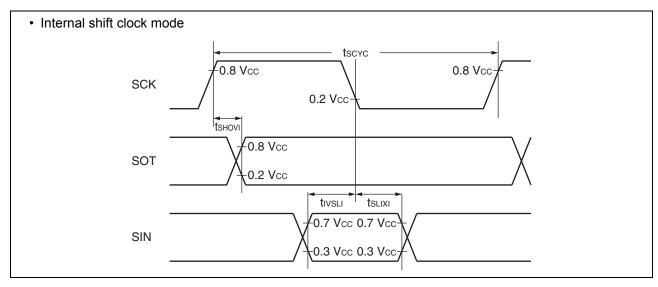
Parameter	Symbol Pin name		Condition	Va	Unit	
Parameter	Symbol	Pin name	Pin name Condition		Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
$SCK^{\uparrow} \rightarrow SOT$ delay time	t shovi	SCK, SOT	Internal clock operation output pin:	-50	+50	ns
Valid SIN $→$ SCK $↓$	tıvslı	SCK, SIN	C _L = 80 pF + 1 TTL	tmcLK*3 + 80	_	ns
SCK↓→ valid SIN hold time	tslixi	SCK, SIN	'	0	_	ns
Serial clock "H" pulse width	t shsl	SCK		3 tmcLK*3 - tR	_	ns
Serial clock "L" pulse width	t slsh	SCK		tmclk*3 + 10	_	ns
$SCK^{\uparrow} \rightarrow SOT$ delay time	t shove	SCK, SOT	External clock	_	2 tмськ* ³ + 60	ns
Valid SIN $→$ SCK $↓$	tivsle	SCK, SIN	operation output pin:	30	_	ns
SCK↓→ valid SIN hold time	tslixe	SCK, SIN	C∟ = 80 pF + 1 TTL	tmcLK*3 + 30	_	ns
SCK falling time	t⊧	SCK		_	10	ns
SCK rising time	t R	SCK		_	10	ns

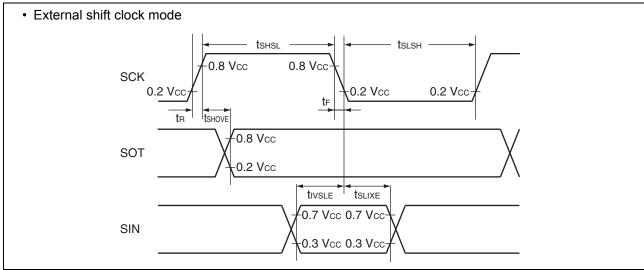
^{*1:} There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

^{*2:} The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

^{*3:} See "Source Clock/Machine Clock" for tMCLK.







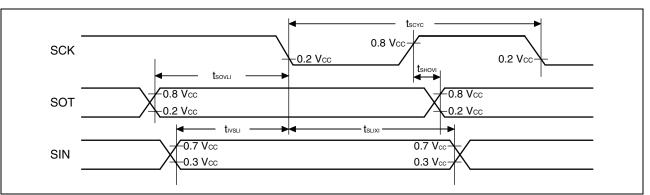


Sampling is executed at the rising edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

Parameter	Symbol	Pin name	Condition	Val	Unit	
Parameter	Symbol	Fill Hallie	Condition	Min	Max	Ullit
Serial clock cycle time	tscyc	SCK		5 t mclk*3	_	ns
SCK [↑] → SOT delay time	t shovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN $→$ SCK $↓$	tıvslı		operation output pin:	tmcLK*3 + 80	_	ns
SCK↓→ valid SIN hold time	t slixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns
SOT → SCK↓delay time	tsovli	SCK, SOT		3tмськ*3 - 70	_	ns

^{*1:} There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

^{*3:} See "Source Clock/Machine Clock" for tmclk.



Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Din nome	Pin name Condition —		Value		
Parameter	Symbol	Fill Hallie	Condition	Min	Max	Unit	
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns	
$SCK\!\!\downarrow \to SOT$ delay time	tslovi	SCK, SOT	Internal clock	-50	+50	ns	
Valid SIN → SCK↑	tıvsнı		operation output pin:	tmclk*3 + 80	_	ns	
$SCK^{\uparrow} \rightarrow valid SIN hold time$	tshixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns	
SOT → SCK [↑] delay time	t sovнı	SCK, SOT		3tмськ*3 - 70	_	ns	

^{*1:} There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

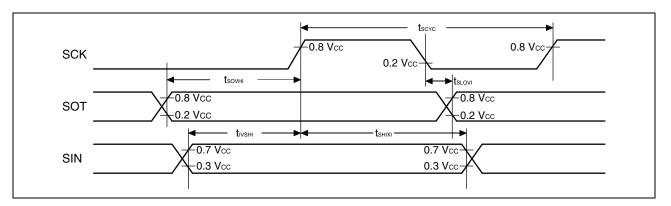
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^{*2:} The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

^{*2:} The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

^{*3:} See "Source Clock/Machine Clock" for tmclk.





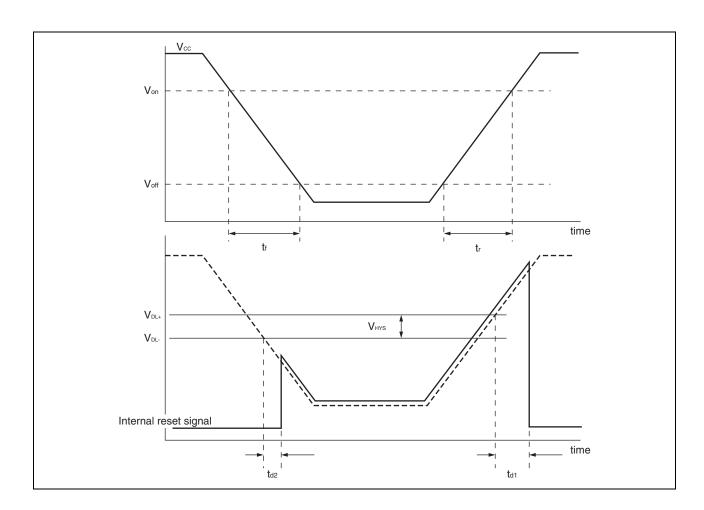
18.4.7 Low-voltage Detection

(Vss = 0.0 V, $T_A = -40^{\circ}C$ to $+85^{\circ}C$)

Doromotor	Symbol		Value		Unit	Pomorko
Parameter	Symbol	Min	Тур	Max	Unit	Remarks
		2.52	2.7	2.88		
Release voltage*	V _{DL+}	2.61	2.8	2.99	V	At nower cumply rice
Release vollage	V DL+	2.89	3.1	3.31	\ \ \	At power supply rise
		3.08	3.3	3.52		
		2.43	2.6	2.77		
Detection voltage*	V _{DL} -	2.52	2.7	2.88	V	At power supply fall
Detection voltage	V DL—	2.80	3	3.20	V	At power supply fair
		2.99	3.2	3.41		
Hysteresis width	VHYS	_	_	100	mV	
Power supply start voltage	Voff	_	_	2.3	V	
Power supply end voltage	Von	4.9	_	_	V	
Power supply voltage change time (at power supply rise)	tr	650	_	_	μs	Slope of power supply that the reset release signal generates within the rating (VDL+)
Power supply voltage change time (at power supply fall)	tf	650	_	_	μs	Slope of power supply that the reset detection signal generates within the rating (VDL-)
Reset release delay time	t d1	_	_	30	μs	
Reset detection delay time	t _{d2}	_	_	30	μs	
LVD reset threshold voltage transition stabilization time	t stb	10	_	_	μs	

^{*:} The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to "CHAPTER 16 LOW-VOLTAGE DETECTION RESET CIRCUIT" in "New 8FX MB95630H Series Hardware Manual".







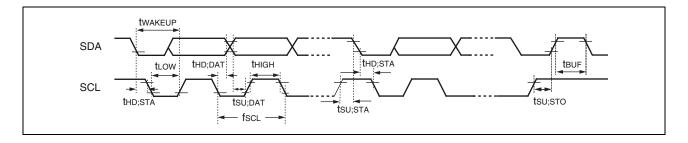
18.4.8 I²C Bus Interface Timing

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ Ta} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Standard- mode		Fast-mode		Unit
				Min	Max	Min	Max	
SCL clock frequency	fscL	SCL		0	100	0	400	kHz
(Repeated) START condition hold time SDA \downarrow \rightarrow SCL \downarrow	thd;sta	SCL, SDA		4.0	_	0.6	_	μs
SCL clock "L" width	tLOW	SCL		4.7	_	1.3	_	μs
SCL clock "H" width	t HIGH	SCL		4.0	_	0.6	_	μs
(Repeated) START condition setup time SCL $\uparrow \rightarrow$ SDA \downarrow	tsu;sta	SCL, SDA	R = 1.7 kΩ, C = 50 pF*1	4.7	_	0.6	_	μs
Data hold time SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$	thd;dat	SCL, SDA	00 pi	0	3.45*2	0	0.9*3	μs
Data setup time SDA $\downarrow \uparrow \rightarrow$ SCL \uparrow	tsu;dat	SCL, SDA		0.25	_	0.1	_	μs
STOP condition setup time SCL $\uparrow \rightarrow$ SDA \uparrow	tsu;sто	SCL, SDA		4	_	0.6	_	μs
Bus free time between STOP condition and START condition	t BUF	SCL, SDA		4.7	_	1.3	_	μs

^{*1:} R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

^{*3:} A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, provided that the condition of tsu;DAT ≥ 250 ns is fulfilled.



^{*2:} The maximum thd; DAT in the Standard-mode is applicable only when the time during which the device is holding the SCL signal at "L" (tLow) does not extend.



 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ TA} = -40^{\circ}\text{C to} + 85^{\circ}\text{C})$

Parameter	Symbol	Pin	Condition	Valu	ue*2	Unit	Remarks	
	Symbol	name	Condition	Min	Max	Unit	Remarks	
SCL clock "L" width	t LOW	SCL		(2 + nm/2)tмсLк – 20	_	ns	Master mode	
SCL clock "H" width	t HIGH	SCL		(nm/2)tмсLк – 20	(nm/2)tмсLк + 20	ns	Master mode	
START condition hold time	thd;sta	SCL, SDA		(-1 + nm/2)tмсLк — 20	(-1 + nm)tмсLк + 20	ns	Master mode Maximum value is applied when m, n = 1, 8. Otherwise, the minimum value is applied.	
STOP condition setup time	t su;sto	SCL, SDA		(1 + nm/2)tмсLк – 20	(1 + nm/2)tмсLк + 20	ns	Master mode	
START condition setup time	tsu;sta	SCL, SDA		(1 + nm/2)tмсLк – 20	(1 + nm/2)tмсLк + 20	ns	Master mode	
Bus free time between STOP condition and START condition	t BUF	SCL, SDA	-R = 1.7 kΩ,	(2 nm + 4) tмсLк – 20	_	ns		
Data hold time	thd;dat	SCL, SDA	$C = 50 \text{ pF}^{*1}$	3 tмсцк — 20	_	ns	Master mode	
Data setup time	tsu;dat	SCL, SDA		(-2 + nm/2) tмсLк — 20	(-1 + nm/2) tмсLк + 20	ns	Master mode It is assumed that "L" of SCL is not extended. The minimum value is applied to the first bit of continuous data. Otherwise, the maximum value is applied.	
Setup time between clearing interrupt and SCL rising	tsu;ınt	SCL		(nm/2) tмсLк — 20	(1 + nm/2) tмсLк + 20	ns	The minimum value is applied to the interrupt at the ninth SCL↓. The maximum value is applied to the interrupt at the eighth SCL↓.	
SCL clock "L" width	t LOW	SCL		4 tмсLк — 20	_	ns	At reception	
SCL clock "H" width	t HIGH	SCL		4 tmcLK - 20	_	ns	At reception	



(Continued)

 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Value* ²		Unit	Remarks
1 diameter	Cyllibol	name	Oonation	Min	Max	Oilit	
START condition detection	t HD;STA	SCL, SDA		2 tmcLK - 20		ns	No START condition is detected when 1 tmcLk is used at reception.
STOP condition detection	t su;sто	SCL, SDA		2 tmclk - 20	_	ns	No STOP condition is detected when 1 tmclk is used at reception.
RESTART condition detection condition	t su;sta	SCL, SDA	R = 1.7 kΩ, C = 50 pF*1	2 tmclk – 20	1	ns	No RESTART condition is detected when 1 tmclk is used at reception.
Bus free time	t BUF	SCL, SDA	О 00 рі	2 tmcLK - 20	-	ns	At reception
Data hold time	t HD;DAT	SCL, SDA		2 tmcLK - 20		ns	At slave transmission mode
Data setup time	tsu;dat	SCL, SDA		tLOW -3 t MCLK -20	1	ns	At slave transmission mode
Data hold time	t HD;DAT	SCL, SDA		0	1	ns	At reception
Data setup time	tsu;dat	SCL, SDA		tмсLк - 20	1	ns	At reception
SDA↓ → SCL↑ (with wakeup function in use)	twakeup	SCL, SDA		Oscillation stabilization wait time +2 tmclk – 20	_	ns	

^{*1:} R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

- m represents the CS[4:3] bits in the I²C clock control register ch. 0 (ICCR0).
- n represents the CS[2:0] bits in the I²C clock control register ch. 0 (ICCR0).
- The actual timing of the I²C bus interface is determined by the values of m and n set by the machine clock (tmclk) and the CS[4:0] bits in the ICCR0 register.
- Standard-mode:

m and n can be set to values in the following range: 0.9 MHz < tmcLk (machine clock) < 16.25 MHz.

The usable frequencies of the machine clock are determined by the settings of m and n as shown below.

 $\begin{array}{lll} (m,\,n)=(1,\,8) & : 0.9 \text{ MHz} < t\text{mclk} \le 1 \text{ MHz} \\ (m,\,n)=(1,\,22),\,(5,\,4),\,(6,\,4),\,(7,\,4),\,(8,\,4) & : 0.9 \text{ MHz} < t\text{mclk} \le 2 \text{ MHz} \\ (m,\,n)=(1,\,38),\,(5,\,8),\,(6,\,8),\,(7,\,8),\,(8,\,8) & : 0.9 \text{ MHz} < t\text{mclk} \le 4 \text{ MHz} \\ (m,\,n)=(1,\,98),\,(5,\,22),\,(6,\,22),\,(7,\,22) & : 0.9 \text{ MHz} < t\text{mclk} \le 10 \text{ MHz} \\ (m,\,n)=(8,\,22) & : 0.9 \text{ MHz} < t\text{mclk} \le 16.25 \text{ MHz} \end{array}$

· Fast-mode:

m and n can be set to values in the following range: 3.3 MHz < tmcLk (machine clock) < 16.25 MHz.

The usable frequencies of the machine clock are determined by the settings of m and n as shown below.

 $\begin{array}{lll} (m,\,n) = (1,\,8) & : 3.3 \text{ MHz} < t_{MCLK} \le 4 \text{ MHz} \\ (m,\,n) = (1,\,22),\,(5,\,4) & : 3.3 \text{ MHz} < t_{MCLK} \le 8 \text{ MHz} \\ (m,\,n) = (1,\,38),\,(6,\,4),\,(7,\,4),\,(8,\,4) & : 3.3 \text{ MHz} < t_{MCLK} \le 10 \text{ MHz} \\ (m,\,n) = (5,\,8) & : 3.3 \text{ MHz} < t_{MCLK} \le 16.25 \text{ MHz} \end{array}$

^{*2: •} See "Source Clock/Machine Clock" for tmclk.

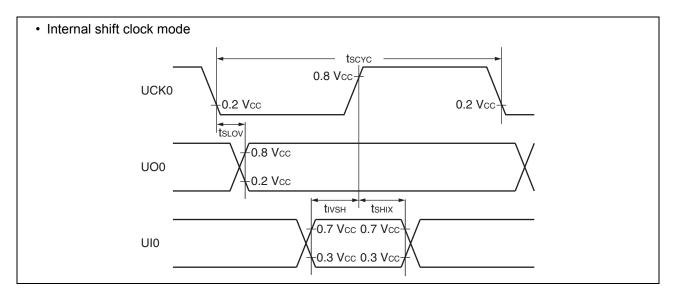


18.4.9 UART/SIO, Serial I/O Timing

 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

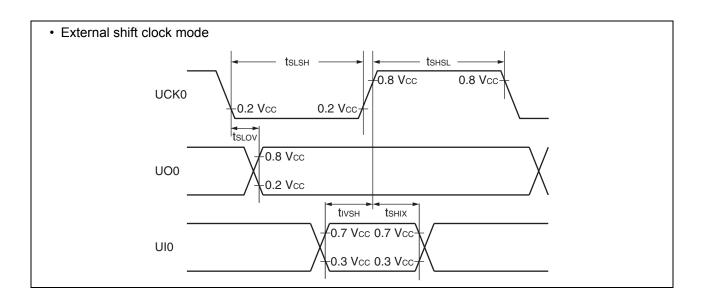
Parameter	Symbol Pin name		Condition	Value		Unit
Parameter	Syllibol	Fili lialile	Condition	Min	Max	Oilit
Serial clock cycle time	tscyc	UCK0		4 t мськ*	_	ns
$UCK \downarrow \to UO$ time	tslov	UCK0, UO0	Internal clock operation	-190	+190	ns
Valid UI → UCK ↑	tıvsh	UCK0, UI0		2 t мськ*	_	ns
UCK ↑ → valid UI hold time	t sнıx	UCK0, UI0		2 t мськ*	_	ns
Serial clock "H" pulse width	t shsl	UCK0		4 t mclk*	_	ns
Serial clock "L" pulse width	t slsh	UCK0	External clock operation	4 t мськ*	_	ns
$UCK \downarrow \to UO$ time	tslov	UCK0, UO0		_	190	ns
Valid UI → UCK ↑	tıvsh	UCK0, UI0		2 tmclk*	_	ns
$UCK \uparrow \rightarrow valid \; UI \; hold \; time$	t sнıx	UCK0, UI0		2 tmclk*		ns

^{*:} See "Source Clock/Machine Clock" for tmclk.



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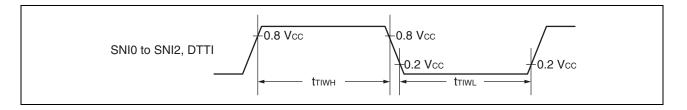




18.4.10 MPG Input Timing

 $(Vcc = 5.0 V\pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name Condition -		Val	ue	Unit	Remarks
Farameter	Syllibol	Fill Hallie	Condition	Min	Max	Oilit	Nemarks
Input pulse width	ttiwh, ttiwl	SNI0 to SNI2, DTTI	_	4 tmclk	_	ns	



18.4.11 Comparator Timing

 $(Vcc = 2.4 V to 5.5 V, Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$

Parameter	Pin name		Value		Unit	Remarks
raiametei	Fill Hallie	Min	Тур	Max	Oilit	Remarks
Voltage range	CMP0_P, CMP0_N	0	_	Vcc - 1.3	V	
Offset voltage	CMP0_P, CMP0_N	-15	_	+15	mV	
Delay time	CMP0 O	_	650	1200	ns	Overdrive 5 mV
Delay tille	CIVIF 0_O	_	140	420	ns	Overdrive 50 mV
Power down delay	CMP0_O	_	_	1200	ns	Power down recovery PD: 1 → 0
Power up stabilization time	CMP0_O	_	_	1200	ns	Output stabilization time at power up



18.5 A/D Converter

18.5.1 A/D Converter Electrical Characteristics

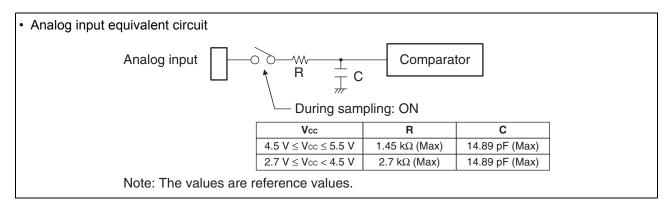
 $(V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{Vss} = 0.0 \text{ V}, \text{TA} = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

			•				
Parameter	Symbol		Value		Unit	Remarks	
raiailletei	i arameter Symbol		Min Typ			Kemarks	
Resolution		_	_	10	bit		
Total error		-3	_	+3	LSB		
Linearity error	—	-2.5	_	+2.5	LSB		
Differential linearity error		-1.9	_	+1.9	LSB		
Zero transition voltage	Vот	Vss – 1.5 LSB	Vss + 0.5 LSB	Vss + 2.5 LSB	V		
Full-scale transition voltage	VFST	Vcc – 4.5 LSB	Vcc – 2 LSB	Vcc + 0.5 LSB	٧		
Compare time	_	3	_	10	μs	$2.7~V \leq Vcc \leq 5.5~V$	
Sampling time	_	0.941	_	∞	μs	$2.7~V \le V_{CC} \le 5.5~V$, with external impedance $< 3.3~k\Omega$ and external capacitance = 10 pF	
Analog input current	lain	-0.3	_	+0.3	μΑ		
Analog input voltage	Vain	Vss		Vcc	V		

18.5.2 Notes on Using A/D Converter

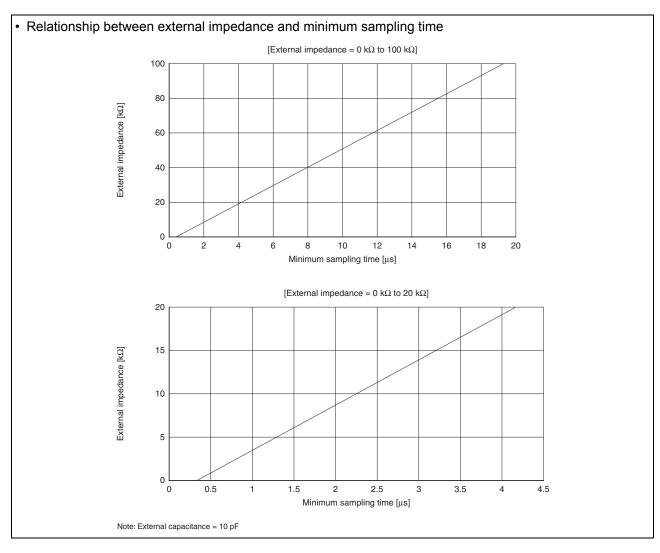
External impedance of analog input and its sampling time

The A/D converter of the MB95630H Series has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 μ F to the analog input pin.



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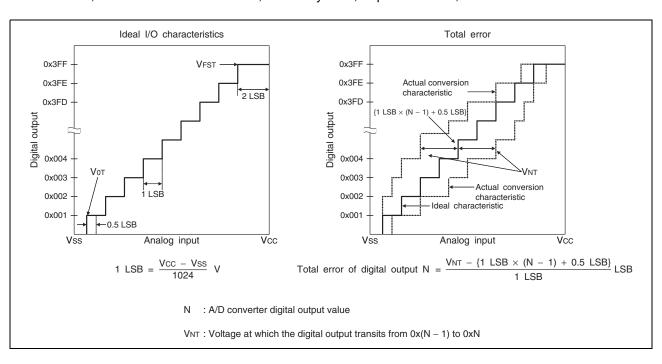
• A/D conversion error

As |Vcc - Vss| decreases, the A/D conversion error increases proportionately.

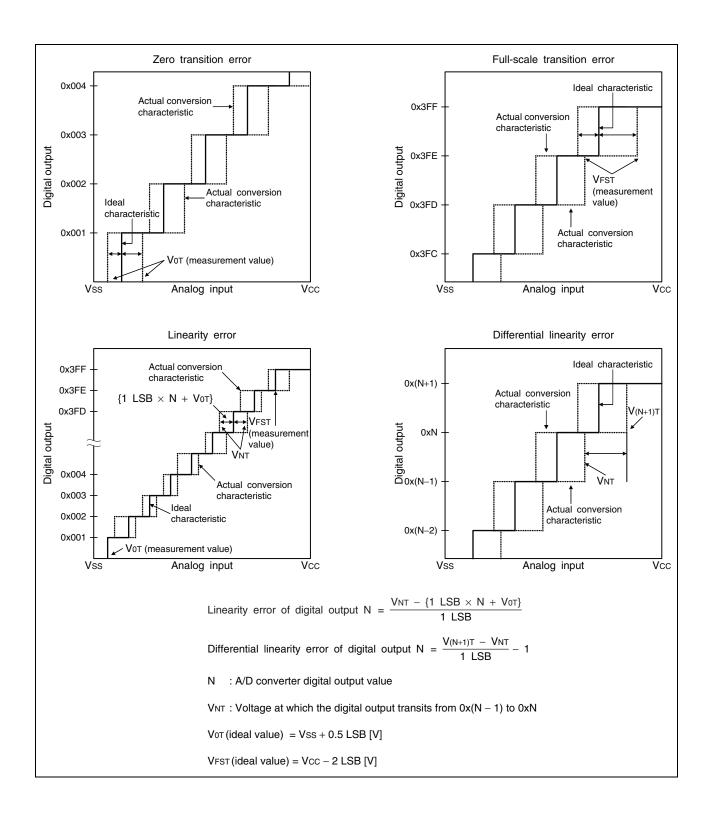


18.5.3 Definitions of A/D Converter Terms

- Resolution
 - It indicates the level of analog variation that can be distinguished by the A/D converter. When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.
- · Linearity error (unit: LSB)
 - It indicates how much an actual conversion value deviates from the straight line connecting the zero transition point ("0000000000" $\leftarrow \rightarrow$ "0000000001") of a device to the full-scale transition point ("1111111111") of the same device.
- Differential linear error (unit: LSB)
 - It indicates how much the input voltage required to change the output code by 1 LSB deviates from an ideal value.
- Total error (unit: LSB)
 - It indicates the difference between an actual value and a theoretical value. The error can be caused by a zero transition error, a full-scale transition errors, a linearity error, a quantum error, or noise.









18.6 Flash Memory Program/Erase Characteristics

Parameter		Value		Unit	Remarks
Parameter	Min	Тур	Max	Ullit	Remarks
Sector erase time (2 Kbyte sector)		0.3*1	1.6*2	s	The time of writing "0x00" prior to erasure is excluded.
Sector erase time (32 Kbyte sector)	_	0.6*1	3.1*2	s	The time of writing "0x00" prior to erasure is excluded.
Byte writing time	_	17	272	μs	System-level overhead is excluded.
Program/erase cycle	100000	_	_	cycle	
Power supply voltage at program/erase	2.4	_	5.5	V	
	20*3	_	_		Average T _A = +85°C Number of program/erase cycles: 1000 or below
Flash memory data retention time	10*³	_	_	year	Average T _A = +85°C Number of program/erase cycles: 1001 to 10000 inclusive
	5* ³	_	_		Average T _A = +85°C Number of program/erase cycles: 10001 or above

^{*1:} Vcc = 5.5 V, IA = +25°C, 0 cycle

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^{*2:} Vcc = 2.4 V, $T_A = +85^{\circ}C$, 100000 cycles

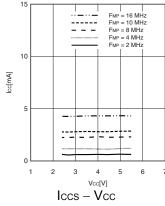
^{*3:} These values were converted from the result of a technology reliability assessment. (These values were converted from the result of a high temperature accelerated test using the Arrhenius equation with the average temperature being +85°C.)



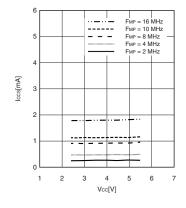
19. Sample Characteristics

· Power supply current temperature characteristics

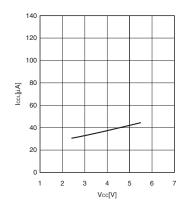
 $T_A = +25^{\circ}C$, $F_{MP} = 2, 4, 8, 10, 16$ MHz (divided by 2) Main clock mode with the external clock operating



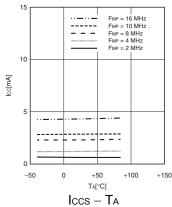
 $T_A = +25^{\circ}C$, $F_{MP} = 2, 4, 8, 10, 16$ MHz (divided by 2) Main sleep mode with the external clock operating



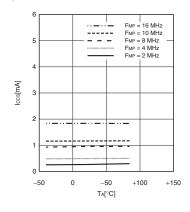
 $I_{CCL} - V_{CC}$ $T_A = +25^{\circ}C, \; F_{MPL} = 16 \; kHz \; (divided \; by \; 2)$ Subclock mode with the external clock operating



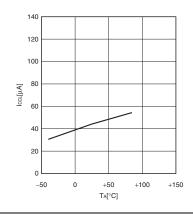
 $V_{CC} = 5.5 \text{ V}, F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main clock mode with the external clock operating



Vcc = 5.5 V, FmP = 2, 4, 8, 10, 16 MHz (divided by 2) Main sleep mode with the external clock operating



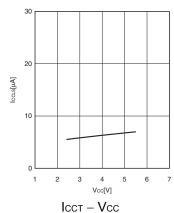
 $I_{CCL} - T_{A}$ $V_{CC} = 5.5 \text{ V}, F_{MPL} = 16 \text{ kHz (divided by 2)}$ Subclock mode with the external clock operating



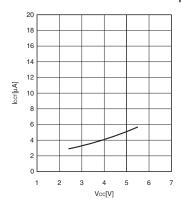




 $T_A = +25^{\circ}C$, $F_{MPL} = 16$ kHz (divided by 2) Subsleep mode with the external clock operating

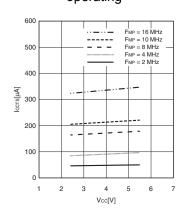


 $T_A = +25$ °C, $F_{MPL} = 16$ kHz (divided by 2) Watch mode with the external clock operating



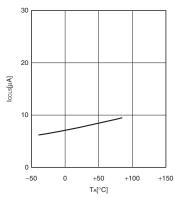
 $\mathsf{Iccts} - \mathsf{Vcc}$

 $T_A = +25^{\circ}C$, $F_{MP} = 2$, 4, 8, 10, 16 MHz (divided by 2) Time-base timer mode with the external clock operating



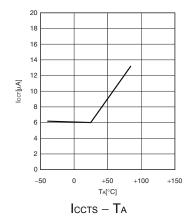
Iccls - Ta

Vcc = 5.5 V, $F_{MPL} = 16 \text{ kHz}$ (divided by 2) Subsleep mode with the external clock operating

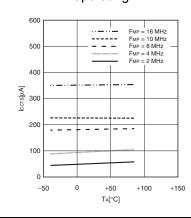


 $I\mathsf{CCT}-T\mathsf{A}$

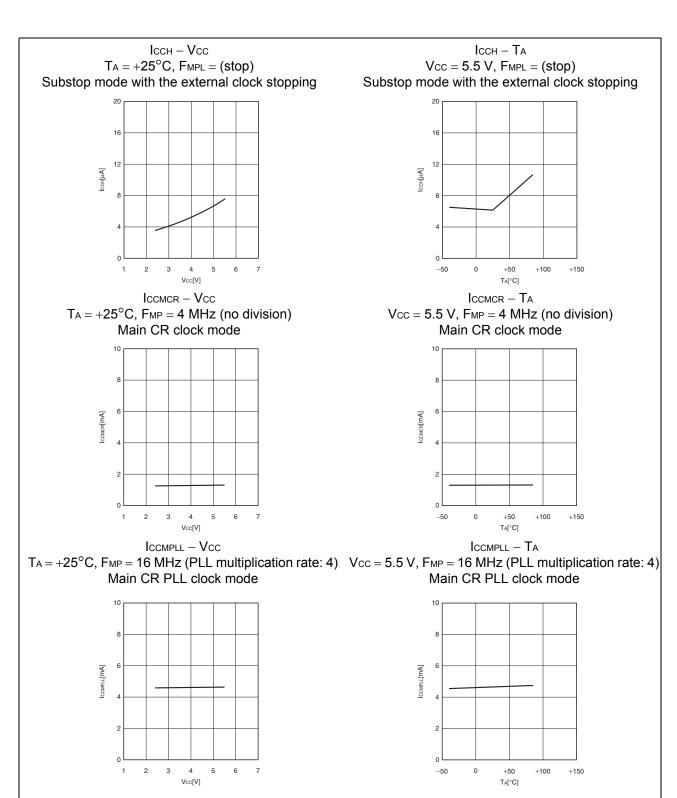
 $V_{CC} = 5.5 \text{ V}, F_{MPL} = 16 \text{ kHz}$ (divided by 2) Watch mode with the external clock operating



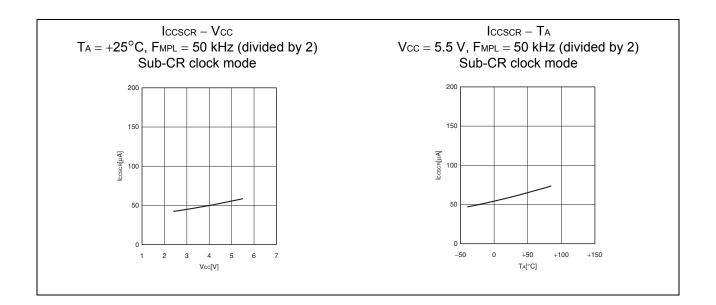
Vcc = 5.5 V, FMP = 2, 4, 8, 10, 16 MHz (divided by 2) Time-base timer mode with the external clock operating



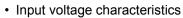


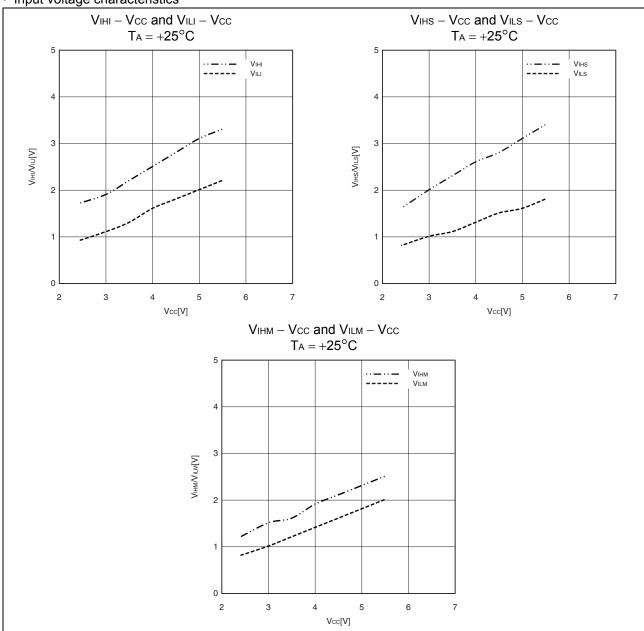






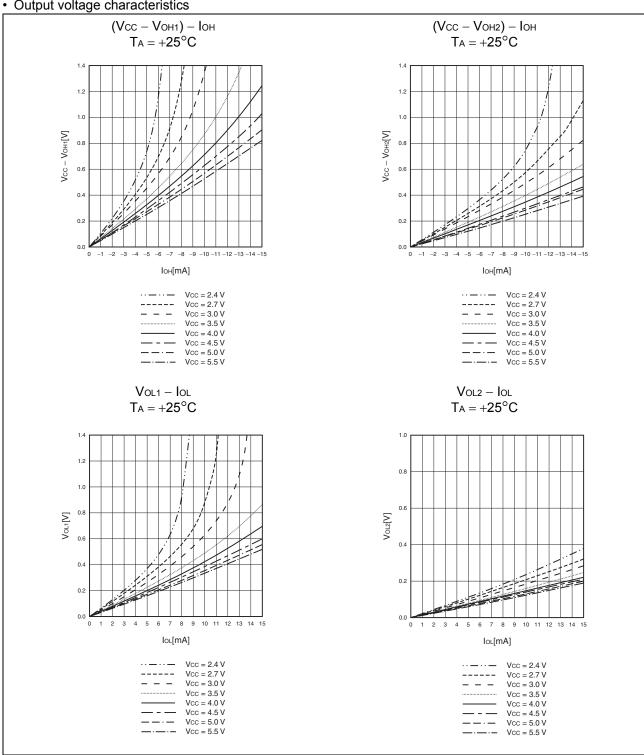






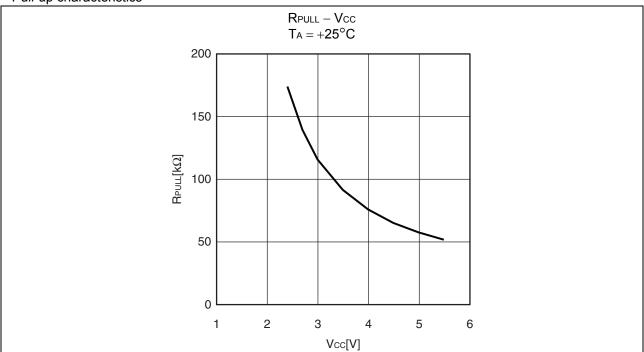


Output voltage characteristics











20. Mask Options

No.	Part number	MB95F632H MB95F633H MB95F634H MB95F636H	MB95F632K MB95F633K MB95F634K MB95F636K	
	Selectable/Fixed	Fixed		
1	Low-voltage detection reset	Without low-voltage detection reset With low-voltage detection		
2	Reset	With dedicated reset input Without dedicated rese		

21. Ordering Information

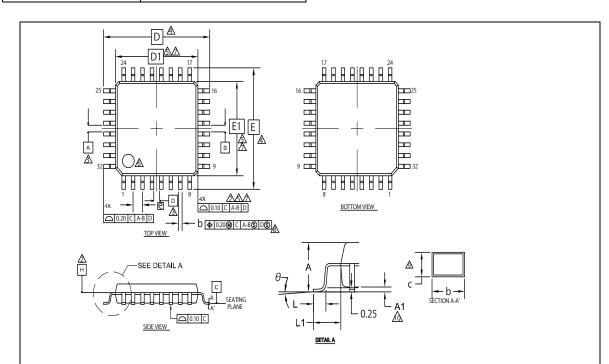
Part number	Package	Packing
MB95F632HPMC-G-SNE2 MB95F632KPMC-G-UNE2 MB95F633HPMC-G-SNE2 MB95F633KPMC-G-UNE2 MB95F634HPMC-G-UNE2 MB95F636HPMC-G-UNE2 MB95F636KPMC-G-UNE2	32-pin plastic LQFP (LQB032)	Tray
MB95F633HPMC-G-UNERE2		Reel
MB95F632HP-G-SH-SNE2 MB95F632KP-G-SH-SNE2 MB95F633HP-G-SH-SNE2 MB95F633KP-G-SH-SNE2 MB95F634HP-G-SH-SNE2 MB95F636HP-G-SH-SNE2 MB95F636HP-G-SH-SNE2 MB95F636KP-G-SH-SNE2	32-pin plastic SH-DIP (PDS032)	Tube
MB95F632HWQN-G-SNE1 MB95F632KWQN-G-SNE1 MB95F633HWQN-G-SNE1 MB95F633KWQN-G-SNE1 MB95F634HWQN-G-SNE1 MB95F636HWQN-G-SNE1 MB95F636HWQN-G-SNE1 MB95F636KWQN-G-SNE1	32-pin plastic QFN (WNP032)	Tray

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22. Package Dimension

Package Type	Package Code
LQFP 32	LQB032



SYMBOL	DIV	MENSIO1	NS
STIVIDUL	MIN.	NOM.	MAX.
А	_	_	1.60
A1	0.05	_	0.15
b	0.32	0.35	0.43
С	0.13	_	0.18
D	9.00 BSC		
D1	7.00 BSC		
е	0.80 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°		8°

NOTES

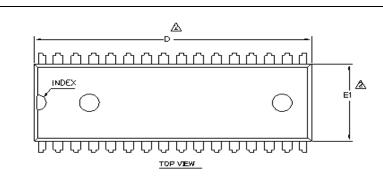
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- ADATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
- ⚠DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
- ⚠ TO BE DETERMINED AT SEATING PLANE C.
- ⚠ DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE.
 DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED
 AT DATUM PLANE H.
- ⚠DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
- AREGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
- ⚠ DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION, THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
- ⚠ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
- 10 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

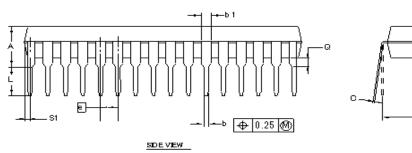
002-13879 **

PACKAGE OUTLINE, 32 LEAD LQFP 7.0X7.0X1.6 MM LQB032 REV*.*



Package Type	Package Code
SDIP 32	PDS032





SYMBOL	DIMENSIONS				
SIMBOL	MIN.	ном.	MAX.		
A	450	4.70	5.40		
L	3.00	3.30	3.50		
D	27.70	28.00	28.20		
E	10.16 BSC				
E1	8.64	8.89	9.14		
8	0°	_	15°		
o	0.20	0.27	0.30		
ь	0.36	0.48	0.56		
ь1	0.82	1.02	1.32		
e	1.778 BSC				
S1			1.27		
œ	0.51				

<u>NOTES</u>

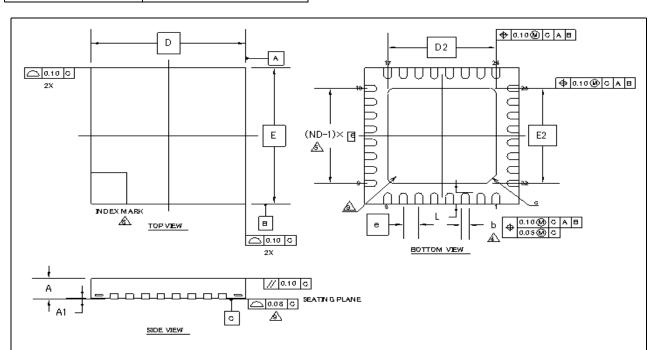
- 1. ALL DIMENSIONS ARE IN MILLIMETER.
- △ DIMENSIONS NOT INCLUDE RESIN REMAINING.
- 3. TERMINAL WIDTH AND TERMINAL THICKNESS INCLUDE PLATING THICKNESS.
- 4. JEDEC SPECIFICATION NO. REF: N/A

PÁCKÁGE OUTLINE, 32 LEÁD FDIP 28,0008,8984, 19 MM FD3032 FEV#

002-16908 **



Package Type	Package Code
QFN 32	WNP032



SYMBOL	DIM ENSIONS		
	MIN.	NOM.	MAX.
Α			0.80
A 1	0.00		0.05
D	5.00 BSC		
E	5.00 BSC		
ь	0.18	0.25	0.30
D ₂	3.50 BSC		
E 2	3.50 BSC		
е	0.50 BSC		
С	0.30 REF		
L	0.35	0.40	0.45

NOTE

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIM ENSIGNING AND TO LERANCING CONFORMS TO ASME Y14.5-1994.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.

⚠DIMENSION "b" APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL. THE DIMENSION "b"SHOULD NOT BE MEASURED IN THAT RADIUS AREA.

⚠ND REFER TO THE NUMBER OF TERMINALS ON D OR ESIDE.

- 6. MAX. PACKAGE WARPAGE IS 0.05mm.
- 7. MAXIMUM ALLOWABLE BURPS IS 0.076 mm IN ALL DIRECTIONS.
- ⚠PIN #1 ID ON TOP WILL BE LOCATED WITHIN INDICATED ZONE.
- ⚠BILATERAL COPLANARITYZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 10. JEDIEC SPECIFICATION NO. REF: N/A

PACKACECUTUNE, 82 LEAD CEN SJOS COOLS MIMYWNDS2 8 SCS SIMMEDAD (SAVA) FIEN

002-15160 **



23. Major Changes In This Edition

Spansion Publication Number: DS702-00009

Page	Section	Details
22	■ PIN CONNECTION • C pin	Corrected the following statement. The bypass capacitor for the Vcc pin must have a capacitance larger than Cs. → The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs.
66	■ ELECTRICAL CHARACTERISTICS 2. Recommended Operating Conditions	Corrected the following statement in remark *2. The bypass capacitor for the Vcc pin must have a capacitance larger than Cs. → The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs.
71	AC Characteristics (1) Clock Timing	Corrected the pin names of the parameter "Input clock rising time and falling time". $X0 \rightarrow X0, X0A$ $X0, X1 \rightarrow X0, X1, X0A, X1A$

NOTE: Please see "Document History" about later revised information.

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Document History Page

Document Title: MB95630H Series, New 8FX 8-bit Microcontrollers Document Number: 002-04627					
Revision	ECN	Orig. of Change	Submission Date	Description of Change	
**	-	AKIH	06/07/2013	Migrated to Cypress and assigned document number 002-04627. No change to document contents or format.	
*A	5193921	AKIH	03/29/2016	Updated to Cypress template Added "MB95F636KPMC-G-UNE2" in "Ordering Information"	
*B	5443796	HTER	02/06/2017	Changed three package codes as the following from "FPT-32P-M30" to "LQB032" from "LCC-32P-M19" to "WNP032" from "DIP-32P-M06" to "PDS032" in chapter: 1.Product Line-up (Page 5) 2.Packages And Corresponding Products (Page 5) 4.Pin Assignment (Page 6, 7) 5.Pin Functions (Page 11) 21.Ordering Information (Page 97) 28.Package Dimensions (Page 98 to 100). Added three Part numbers - MB95F632KPMC-G-UNE2 - MB95F633KPMC-G-UNE2 - MB95F633KPMC-G-UNE2 in chapter 21.Ordering Information (Page 97). Deleted four Part numbers - MB95F632KPMC-G-SNE2 - MB95F633KPMC-G-SNE2 - MB95F633KPMC-G-SNE2 - MB95F634KPMC-G-SNE2 - MB95F636KPMC-G-SNE2 - MB95F636KPMC-G-SNE2 in chapter 21.Ordering Information (Page 97).	
*C	5746267	AESATP12	05/23/2017	Updated logo and copyright.	
*D	5895915	HUAL	09/27/2017	Added Part number "MB95F633HPMC-G-UNERE2" and Packing information Modified from "MB95F634HPMC-G-SNE2" to "MB95F634HPMC-G-UNE2" in 21.Ordering Information (Page 97)	

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